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Total Ionizing Dose Test Report

No. 21T-RTAX2000S-CQ352-DHK3S1

February 2021

Table of Contents

I. Summary Table	3
II. Total Ionizing Dose (TID) Testing	3
A. Device-Under-Test (DUT) and Irradiation Parameters	3
B. Test Method	4
C. Design and Parametric Measurements	5
III. Test Results	6
A. Functionality.....	6
B. Power Supply Current (ICCA and ICCI)	6
C. Single-Ended Input Logic Threshold (VIL/VIH)	10
D. Differential Input (LVPECL) Threshold Voltage (VIL/VIH)	11
E. Output-Drive Voltage (VOL/VOH).....	12
F. Propagation Delay.....	13
G. Transition Characteristics	15
Appendix A: DUT Bias	27
Appendix B: DUT Design Schematics and Verilog Files	29

TOTAL IONIZING DOSE TEST REPORT
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January 7, 2021

I. Summary Table

Parameter	Tolerance
1. Gross Functionality	Passed 300 krad (SiO ₂)
2. Power Supply Current (ICCA/ICCI)	Passed 300 krad (SiO ₂)
3. Input Threshold (VTIL/VIH)	Passed 300 krad (SiO ₂)
4. Output Drive (VOL/VOH)	Passed 300 krad (SiO ₂)
5. Propagation Delay	Passed 300 krad (SiO ₂) for 10% degradation criterion
6. Transition Characteristics	Passed 300 krad (SiO ₂)

II. Total Ionizing Dose (TID) Testing

This testing is designed on the base of an extensive database (see TID data of antifuse-based FPGAs at <http://www.klabs.org> and <http://www.microsemi.com/soc>) accumulated from the TID testing of many generations of antifuse-based FPGAs.

A. Device-Under-Test (DUT) and Irradiation Parameters

Table 1 lists the DUT and irradiation parameters. During irradiation, each input and most of the output is grounded through a 1 MΩ resistor; during annealing, each input or output is tied to the ground or VCCI with a 2.7 kΩ resistor. Appendix A contains the schematics of the irradiation-bias circuit.

Table 1 DUT and Irradiation Parameters

Part Number	RTAX2000S
Package	CQ352
Foundry	United Microelectronics Corp.
Technology	0.15 μm CMOS
DUT Design	TOP_AX2000S_TID
Die Lot Number	DHK3S1
Quantity Tested	6
Serial Number	300 krad(SiO ₂): 13298, 13304 200 krad(SiO ₂): 13273, 13280 100 krad(SiO ₂): 13260, 13267
Radiation Facility	Defense Microelectronics Activity
Radiation Source	Co-60
Dose Rate (±5%)	10 krad(SiO ₂)/min
Irradiation Temperature	Room
Irradiation and Measurement Bias (VCCI/VCCA)	Static at 3.3 V/1.5 V

B. Test Method

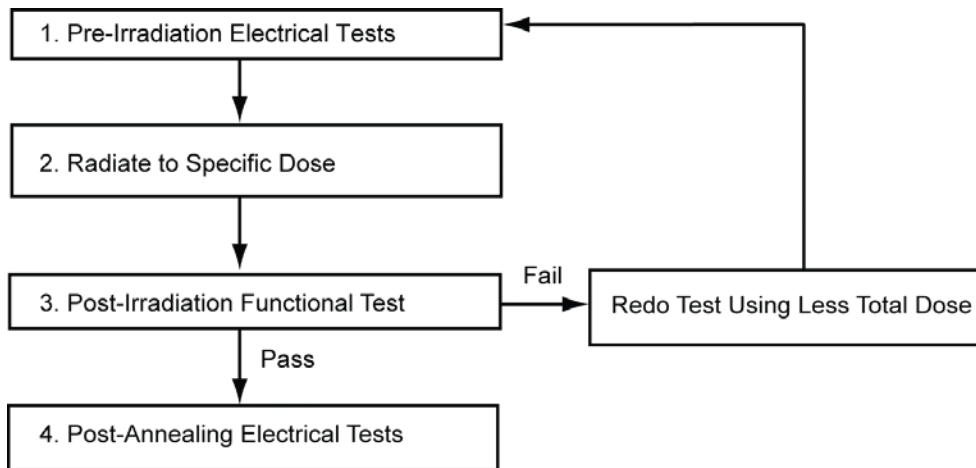


Figure 1 Parametric Test Flow Chart

The test method generally follows the guidelines in the military standard TM1019.8. Figure 1 is the flow chart describing the steps for functional and parametric tests, irradiation, and post-irradiation annealing.

The accelerated aging, or rebound test mentioned in TM1019.8, is unnecessary; because there is no adverse time-dependent effect (TDE) in Microsemi products manufactured by deep sub-micron CMOS technologies. Elevated temperature annealing basically reduces the effects originating from radiation-induced leakage currents. As indicated by test data in the following sections, the predominant radiation effects in RTAX2000S are due to radiation-induced leakage currents.

Room temperature annealing is performed in this test; the duration is approximately 7 days.

C. Design and Parametric Measurements

The DUT uses a high utilization, generic design (TOP_AX2000S_TID) to evaluate total dose effects for typical space applications. Appendix B contains the schematics and Verilog files of this design.

Table 2 lists measured electrical parameters and the corresponding logic design. The functionality is measured on the output pin (O_BS) of a combinational buffer-string with 14,000 buffers, output pins (O_ANDP_CLKF, O_ORP_CLKF, O_FF_CLKF, O_ANDC_CLKF, O_ORC_CLKF, O_ANDP_CLKG, O_ORP_CLKG, O_FF_CLKG, O_ANDC_CLKG, O_ORC_CLKG, O_ANDP_CLKH, O_ORP_CLKH, O_FF_CLKH, O_ANDC_CLKH, O_ORC_CLKH, O_ANDP_HCLKA, O_ORP_HCLKA, O_FF_HCLKA, O_ANDC_HCLKA, and O_ORC_HCLKA) of four (4) shift registers with 10,728 bits total, and half of the output pins (OUTX0, OUTX1, OUTX2, OUTX3, OUTX4, OUTX5, OUTX6 and OUTX7) of the embedded RAM configured as 16K×16.

ICC is measured on the power supply of the logic-array (ICCA) and I/O (ICCI) respectively. The input logic threshold (VIL/VIH) is measured on single-ended inputs EN8, DA, IO_11, IO_12, IO_13, IO_14, IO_15 and IO_16, and also on differential inputs DIO_11P, DIO_12P, DIO_13P, DIO_14P, DIO_15P, DIO_16P and DIO_17P. The differential inputs are configured as LVPECL instead of LVDS; because LVPECL using 3.3 VDC, is worse than LVDS which uses 2.5 VDC. During the measurement on the differential inputs, the N (negative) side of the differential pair is biased at 1.8 V. The output-drive voltage (VOL/VOH) is measured on QA0 and YQ0. The propagation delay is measured on the output (O_BS) of the buffer string; the definition is the time delay from the triggering edge at the CLOCK input to the switching edge at the output O_BS. Both the delays of low-to-high and high-to-low output transitions are measured; the reported delay is the average of these two measurements. The transition characteristics, measured on the output O_BS, are shown as oscilloscope captures.

Table 2 Logic Design for Parametric Measurements

Parameters	Logic Design
1. Functionality	All key logic functions (O_BS, O_ANDP_CLKF, O_ORP_CLKF, O_FF_CLKF, O_ANDC_CLKF, O_ORC_CLKF, O_ANDP_CLKG, O_ORP_CLKG, O_FF_CLKG, O_ANDC_CLKG, O_ORC_CLKG, O_ANDP_CLKH, O_ORP_CLKH, O_FF_CLKH, O_ANDC_CLKH, O_ORC_CLKH, O_ANDP_HCLKA, O_ORP_HCLKA, O_FF_HCLKA, O_ANDC_HCLKA, and O_ORC_HCLKA), and outputs of embedded RAM (OUTX0, OUTX1, OUTX2, OUTX3, OUTX4, OUTX5, OUTX6 and OUTX7)
2. ICC (ICCA/ICCI)	DUT power supply
3. Input Threshold (VIL/VIH)	Single ended inputs (EN8/YQ0, DA/QA0, IO_11/IO_01, IO_12/IO_02, IO_13/IO_03, IO_14/IO_04, IO_15/IO_05, IO_16/IO_06), and differential inputs (DIO_11P/DIO_01, DIO_12P/DIO_02, DIO_13P/DIO_03, DIO_14P/DIO_04, DIO_15P/DIO_05, DIO_16P/DIO_06, DIO_17P/DIO_07)
4. Output Drive (VOL/VOH)	Output buffer (EN8/YQ0, DA/QA0)
5. Propagation Delay	String of buffers (CLOCK to O_BS)
6. Transition Characteristic	String of buffers output (O_BS)

III. Test Results

A. Functionality

Every DUT passed the pre-irradiation and post-annealing functional tests. The as-irradiated DUT is functionally tested on the output (O_FF_HCLKA) of the largest shift register.

B. Power Supply Current (ICCA and ICCI)

Figure 2 through Figure 7 plot the influx standby ICCA and ICCI versus total dose for each DUT. The post-annealing ICC for four different bit patterns, all '0', all '1', checkerboard and inverted-checkerboard, in the RAM are basically the same.

Table 3 summarizes the pre-irradiation, post-irradiation right after irradiation and before anneal, and post-annealing ICCA and ICCI data.

Table 3 Pre-Irradiation, Post Irradiation and Post-Annealing ICC

DUT	Total Dose	ICCA (mA)			ICCI (mA)		
		Pre-irrad	Post-irrad	Post-ann	Pre-irrad	Post-irrad	Post-ann
13260	100 krad	1.4	1.5	1.0	26.1	28.8	27.3
13267	100 krad	1.6	2.1	1.4	26.6	28.9	27.7
13273	200 krad	1.0	3.6	1.1	26.3	60.6	37.4
13280	200 krad	1.2	4.0	1.1	25.9	57.6	36.7
13298	300 krad	1.1	91.1	8.9	26.3	128	55.2
13304	300 krad	1.2	115	13.7	26.2	121	53.0

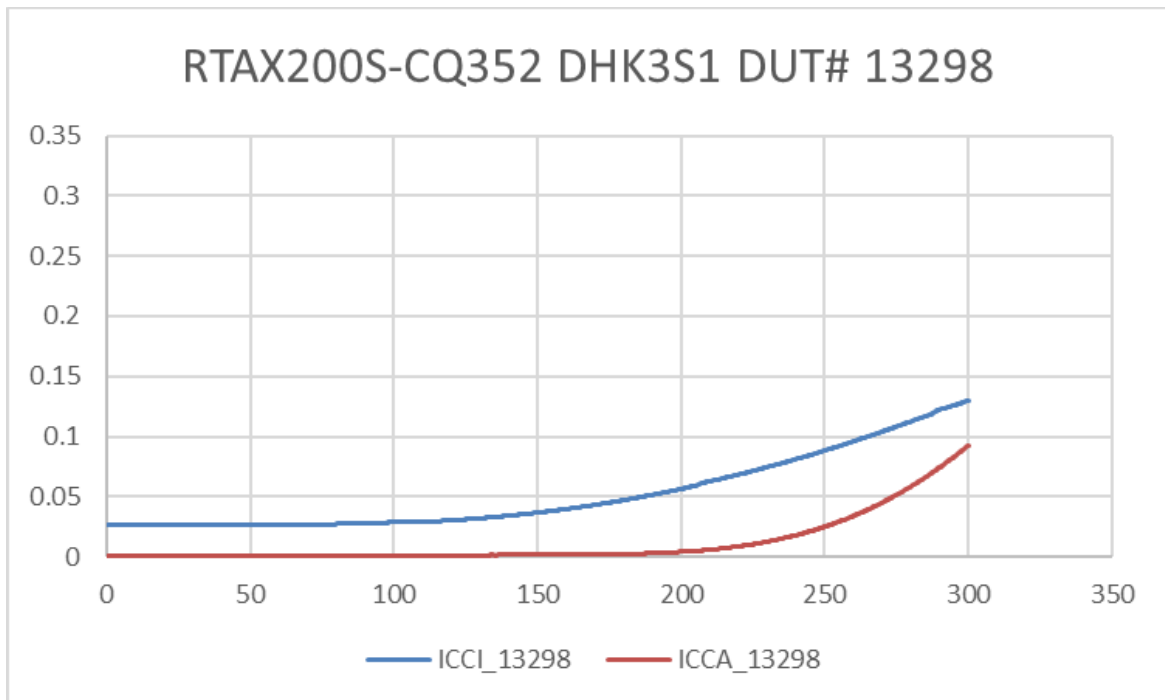


Figure 2 DUT 13298 Influx ICCA and ICCI

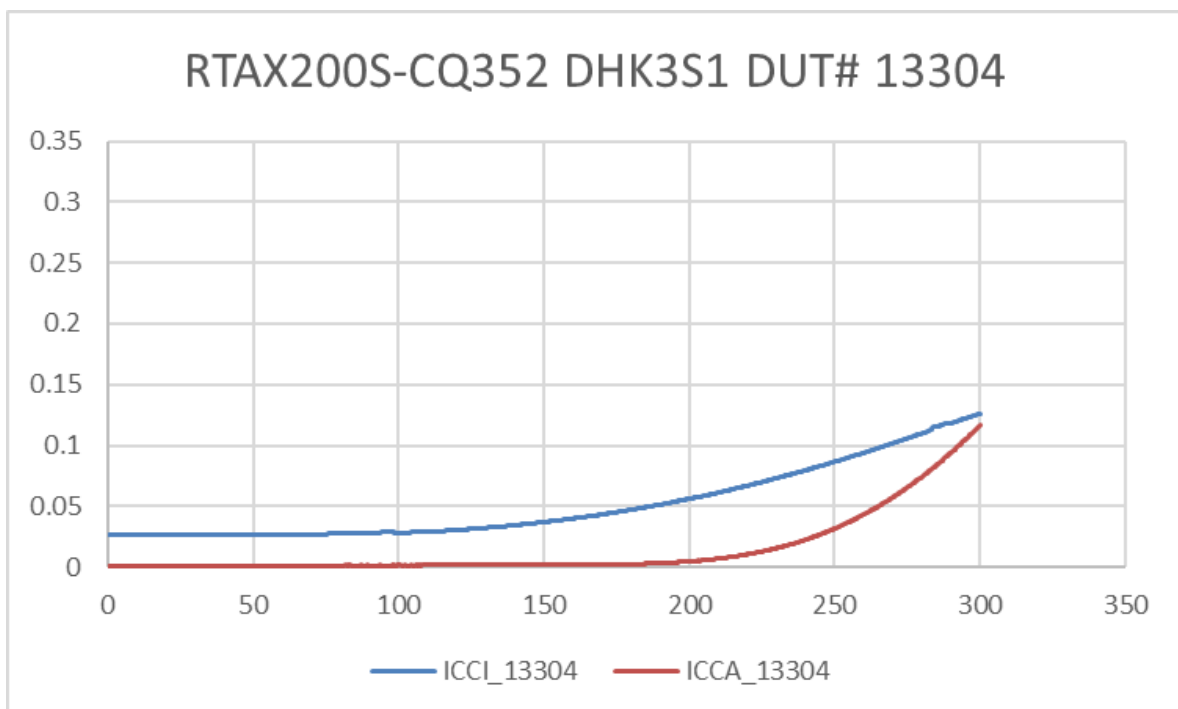


Figure 3 DUT 13304 Influx ICCA and ICCI

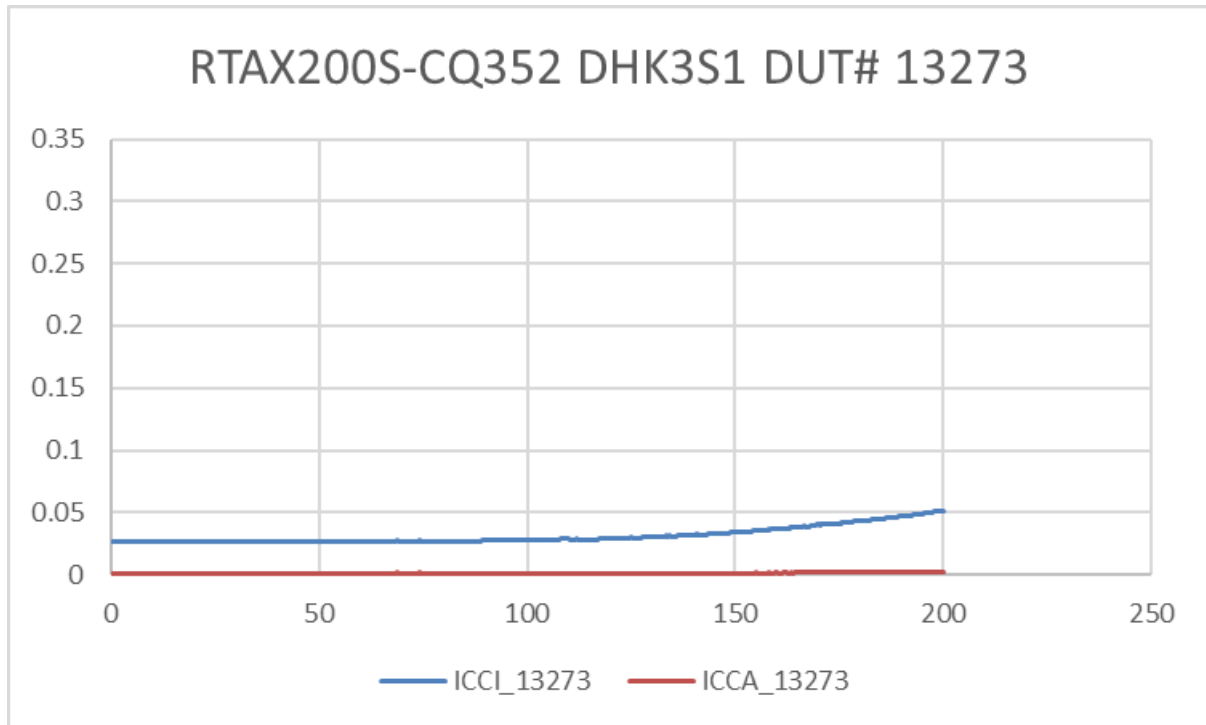


Figure 4 DUT 13273 Influx ICCA and ICCI

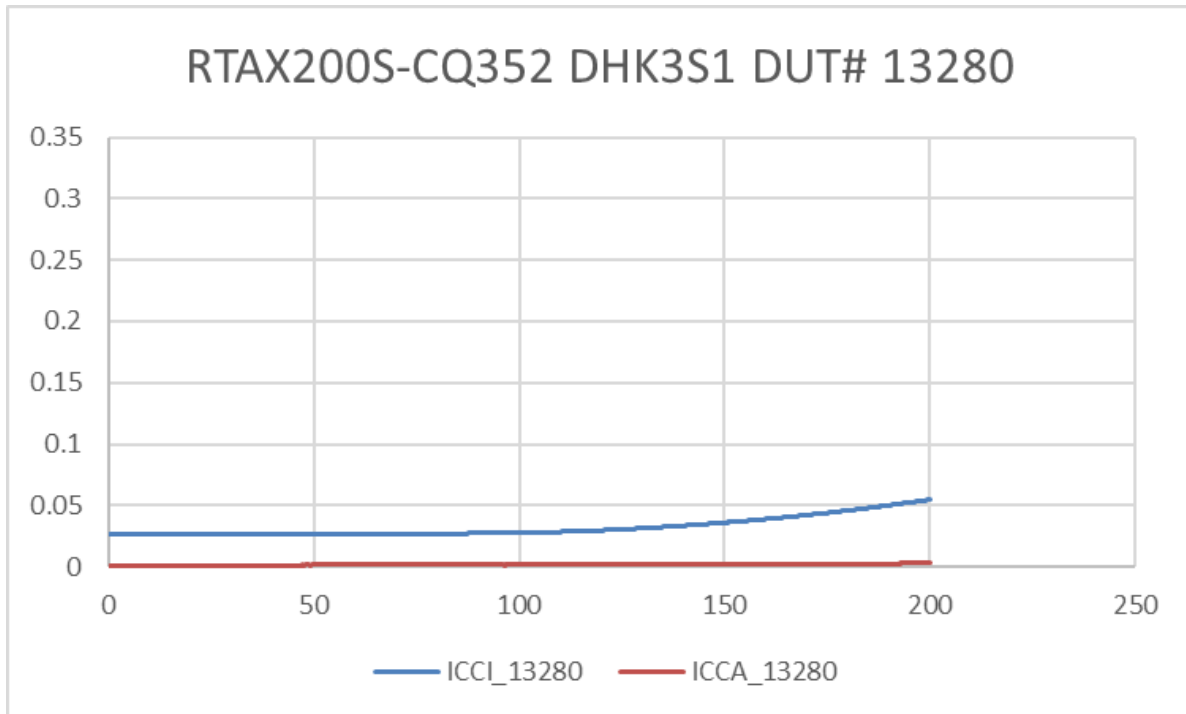


Figure 5 DUT 13280 Influx ICCA and ICCI

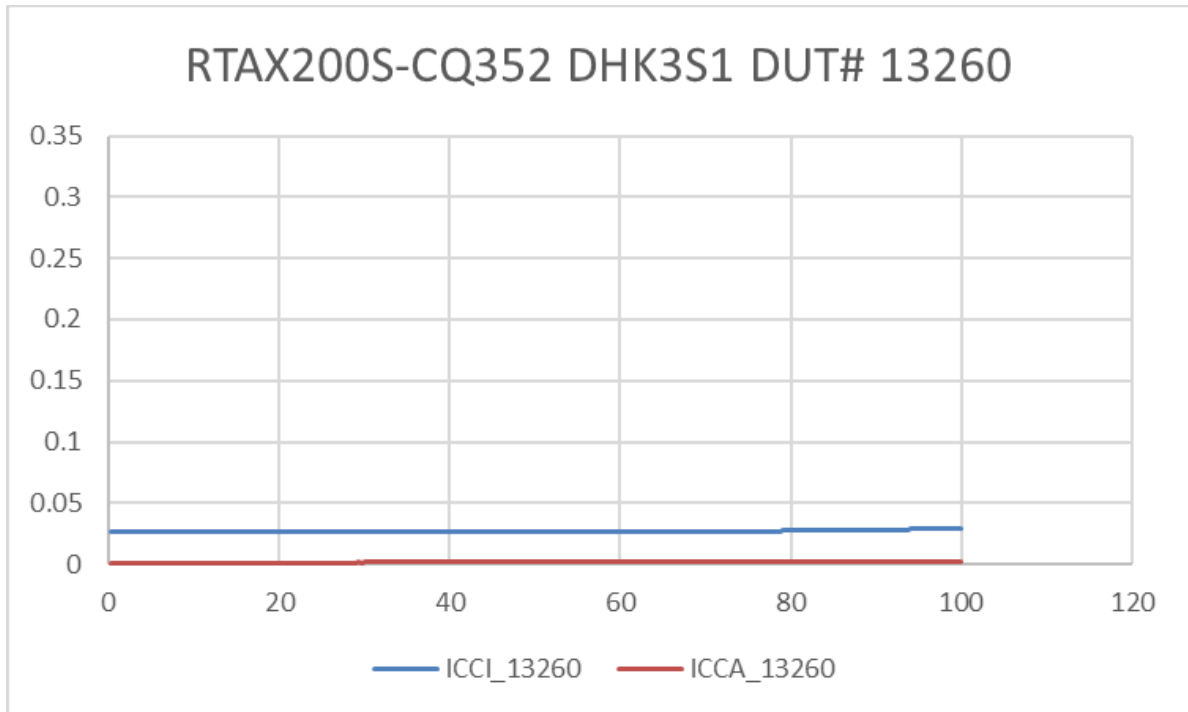


Figure 6 DUT 13260 Influx ICCA and ICCI

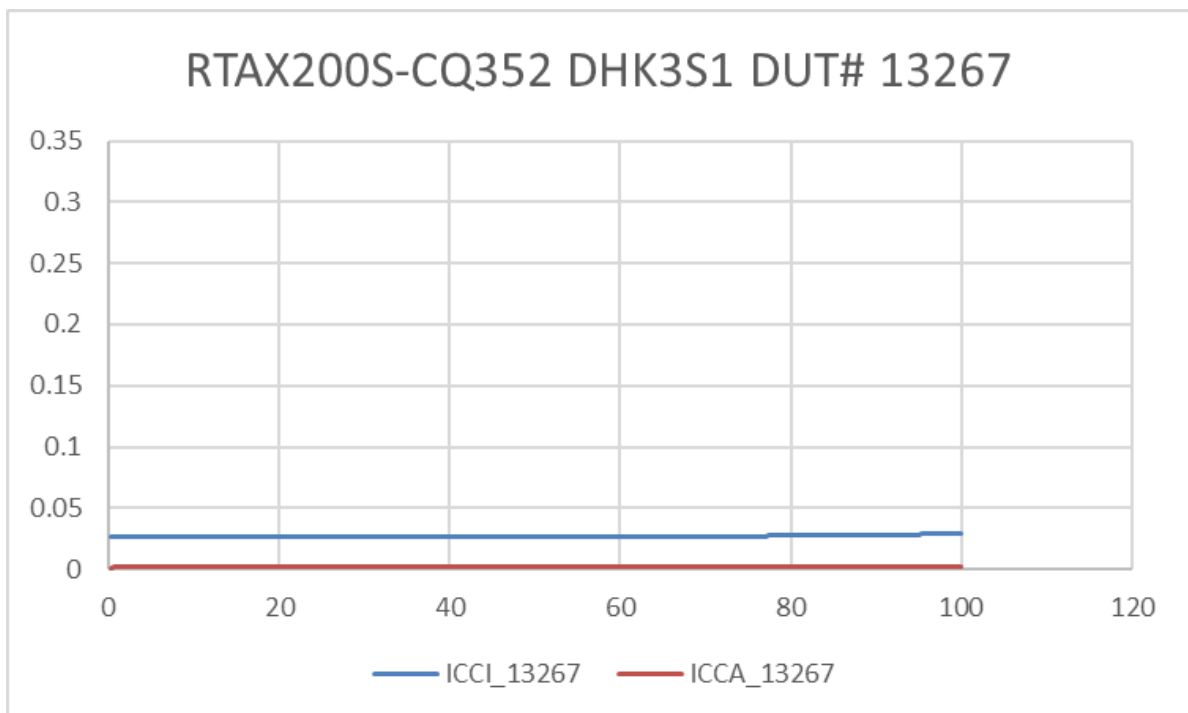


Figure 7 DUT 13267 Influx ICCA and ICCI

C. Single-Ended Input Logic Threshold (VIL/VIH)

Table 4a through Table 4c list the pre-irradiation and post-annealing single-ended input logic thresholds. All data are within the specification limits. The post-annealing shift in every case is very small.

Table 4a Pre-Irradiation and Post-Annealing Input Thresholds

DUT	13298 (300 krad)				13304 (300 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DA	1395	1375	1375	1365	1400	1380	1375	1365
EN8	1365	1355	1375	1365	1385	1355	1375	1345
IO_I_6	1370	1370	1375	1370	1375	1375	1380	1370
IO_I_5	1360	1360	1385	1375	1360	1360	1385	1375
IO_I_4	1370	1370	1380	1370	1370	1360	1380	1370
IO_I_3	1340	1325	1405	1415	1340	1325	1405	1395
IO_I_2	1370	1365	1395	1385	1370	1360	1390	1385
IO_I_1	1370	1360	1390	1385	1365	1365	1390	1380

Table 4b Pre-Irradiation and Post-Annealing Input Thresholds

DUT	13273 (200 krad)				13280 (200 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DA	1390	1375	1370	1360	1395	1375	1370	1365
EN8	1360	1345	1370	1350	1360	1360	1365	1365
IO_I_6	1355	1360	1370	1365	1370	1375	1375	1370
IO_I_5	1370	1350	1380	1370	1355	1360	1380	1375
IO_I_4	1370	1355	1375	1365	1365	1360	1370	1370
IO_I_3	1330	1320	1415	1390	1340	1325	1405	1395
IO_I_2	1355	1355	1390	1380	1365	1360	1390	1380
IO_I_1	1360	1355	1385	1375	1375	1365	1390	1385

Table 4c Pre-Irradiation and Post-Annealing Input Thresholds

DUT	13260 (100 krad)				13267 (100 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DA	1415	1395	1380	1375	1410	1395	1380	1375
EN8	1385	1360	1375	1375	1390	1360	1380	1370
IO_I_6	1405	1375	1390	1380	1395	1370	1385	1370
IO_I_5	1390	1365	1395	1390	1390	1360	1390	1380
IO_I_4	1385	1370	1385	1375	1375	1370	1385	1375
IO_I_3	1350	1330	1415	1410	1345	1325	1405	1405
IO_I_2	1375	1370	1400	1395	1385	1370	1400	1395
IO_I_1	1375	1370	1395	1390	1375	1370	1395	1390

D. Differential Input (LVPECL) Threshold Voltage (VIL/VIH)

Table 5a through Table 5c list the LVPECL differential input threshold voltage changes due to irradiations. All pins show negligible changes, and all the data are within the specification.

Table 5a Pre-Irradiation and Post-Annealing Differential Input Thresholds

DUT	13298 (300 krad)				13304 (300 krad)			
	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DIO_IP_1	1795	1795	1790	1790	1795	1790	1790	1790
DIO_IP_2	1790	1790	1790	1790	1790	1790	1795	1795
DIO_IP_3	1795	1795	1790	1790	1790	1790	1785	1785
DIO_IP_4	1790	1790	1795	1795	1785	1790	1790	1790
DIO_IP_5	1790	1790	1790	1790	1790	1790	1785	1785
DIO_IP_6	1780	1775	1785	1785	1785	1785	1790	1790
DIO_IP_7	1795	1795	1790	1795	1795	1795	1790	1790

Table 5b Pre-Irradiation and Post-Annealing Differential Input Thresholds

DUT	13273 (200 krad)				13280 (200 krad)			
	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DIO_IP_1	1795	1790	1790	1790	1790	1790	1785	1785
DIO_IP_2	1790	1790	1790	1790	1790	1790	1790	1790
DIO_IP_3	1790	1790	1785	1785	1795	1795	1790	1790
DIO_IP_4	1780	1775	1775	1785	1780	1785	1790	1790
DIO_IP_5	1795	1795	1795	1790	1785	1785	1780	1780
DIO_IP_6	1780	1780	1790	1790	1780	1780	1785	1785
DIO_IP_7	1790	1790	1790	1785	1790	1790	1790	1790

Table 5c Pre-Irradiation and Post-Annealing Differential Input Thresholds

DUT	13260 (100 krad)				13267 (100 krad)			
	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DIO_IP_1	1795	1795	1790	1790	1795	1795	1790	1790
DIO_IP_2	1785	1785	1785	1785	1780	1780	1780	1780
DIO_IP_3	1790	1790	1785	1785	1795	1795	1790	1790
DIO_IP_4	1780	1780	1790	1790	1785	1785	1795	1795
DIO_IP_5	1790	1790	1790	1790	1790	1790	1790	1790
DIO_IP_6	1790	1775	1785	1785	1785	1780	1790	1790
DIO_IP_7	1795	1795	1795	1795	1785	1790	1785	1785

E. Output-Drive Voltage (VOL/VOH)

The pre-irradiation and post-annealing VOL/VOH are listed in Tables 6 and 7. The post-annealing data are within the specification limits.

Table 6 Pre-Irradiation and Post-Annealing VOL (mV) at Various Sinking Current

Sourcing Current	Pin\DUT	13298 (300 krad)		13304 (300 krad)		13273 (200 krad)		13280 (200 krad)		13260 (100 krad)		13267 (100 krad)	
		Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an
1 mA	QA0	8	7	9	7	8	7	8	7	9	8	8	7
	YQ0	9	8	9	8	9	9	9	8	9	8	9	8
12 mA	QA0	93	89	93	89	93	89	92	89	93	90	94	90
	YQ0	102	96	102	97	101	96	101	96	102	97	103	98
20 mA	QA0	155	149	155	149	155	149	154	148	156	151	157	151
	YQ0	170	161	170	162	169	161	169	160	170	163	171	164
50 mA	QA0	395	379	395	379	395	381	393	378	396	385	398	386
	YQ0	431	409	432	410	428	409	427	407	431	414	434	416
100 mA	QA0	840	804	841	806	841	809	834	803	843	819	845	819
	YQ0	913	864	914	868	908	865	905	860	912	877	919	880

Table 7 Pre-Irradiation and Post-Annealing VOH (mV) at Various Sourcing Current

Sourcing Current	Pin\DUT	13298 (300 krad)		13304 (300 krad)		13273 (200 krad)		13280 (200 krad)		13260 (100 krad)		13267 (100 krad)	
		Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an
1 mA	QA0	3289	3284	3289	3284	3289	3286	3289	3285	3289	3287	3289	3287
	YQ0	3288	3284	3288	3284	3288	3286	3288	3285	3288	3287	3289	3287
8 mA	QA0	3221	3216	3221	3216	3221	3217	3222	3218	3222	3220	3222	3220
	YQ0	3215	3212	3215	3212	3216	3214	3216	3214	3216	3216	3217	3216
20 mA	QA0	3102	3097	3102	3096	3102	3098	3103	3100	3103	3102	3105	3103
	YQ0	3089	3088	3089	3087	3090	3091	3091	3091	3091	3093	3091	3092
50 mA	QA0	2789	2784	2788	2782	2788	2785	2791	2789	2793	2792	2795	2794
	YQ0	2758	2760	2757	2758	2761	2764	2762	2767	2762	2768	2764	2771
100 mA	QA0	2173	2167	2170	2162	2169	2165	2179	2177	2184	2184	2191	2190
	YQ0	2112	2120	2109	2114	2118	2128	2123	2136	2124	2137	2133	2146

F. Propagation Delay

The propagation delay was measured in-situ, post-irradiation, and post-annealing. The results are plotted in Figure 8, and listed in Table 8. As shown in Figure 8, the propagation delay moves with the total dose, but the change is small throughout the irradiation. Referring to influx static current plots (Figure 2 through Figure 7), a device probably heats up as the dose increases. The rising temperature could be the root cause of the increasing trend at high doses. The post-annealing data, on the other hand, show decreased delay in every case.

The radiation delta in every case is well within the 10% degradation criterion. The user can take the worst case for the design margin consideration.

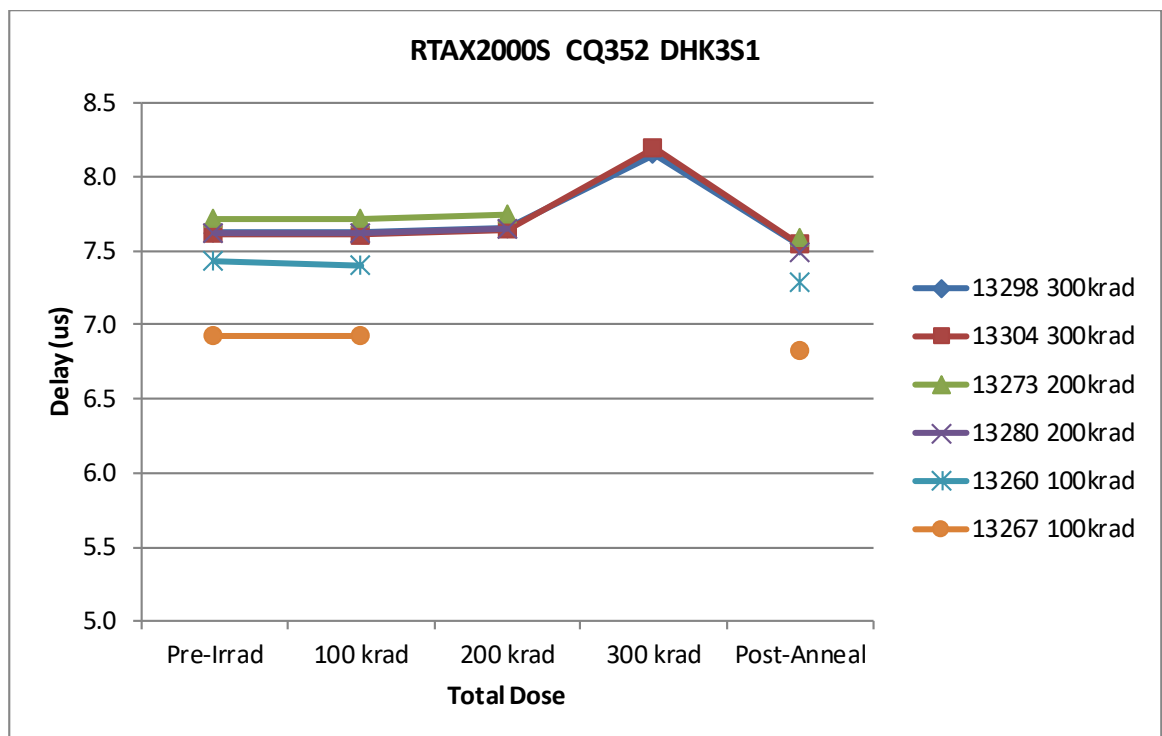


Figure 8 In-Situ Propagation Delay versus Total Dose

Table 8 Radiation-Induced Propagation Delay Degradations

Delay (μ s)							
	DUT	Total Dose	Pre-rad	100 krad	200 krad	300 krad	Post-ann
	13298	300 krad	7.62	7.62	7.66	8.15	7.54
	13304	300 krad	7.62	7.61	7.65	8.20	7.54
	13273	200 krad	7.72	7.72	7.75	-	7.59
	13280	200 krad	7.62	7.62	7.65	-	7.50
	13260	100 krad	7.43	7.40	-	-	7.29
	13267	100 krad	6.93	6.93	-	-	6.82
Radiation Δ (%)							
	DUT	Total Dose	Pre-rad	100 krad	200 krad	300 krad	Post-ann
	13298	300 krad	-	0.00%	0.46%	6.96%	-1.12%
	13304	300 krad	-	-0.07%	0.39%	7.62%	-0.98%
	13273	200 krad	-	0.00%	0.39%	-	-1.62%
	13280	200 krad	-	0.00%	0.39%	-	-1.64%
	13260	100 krad	-	-0.40%	-	-	-1.95%
	13267	100 krad	-	0.00%	-	-	-1.52%

G. Transition Characteristics

Figure 9a to Figure 20b show the pre-irradiation and post-annealing transition edges. In each case, the radiation-induced transition-time degradation is insignificant.



Figure 9a DUT 13298 Pre-Irradiation Rising Edge

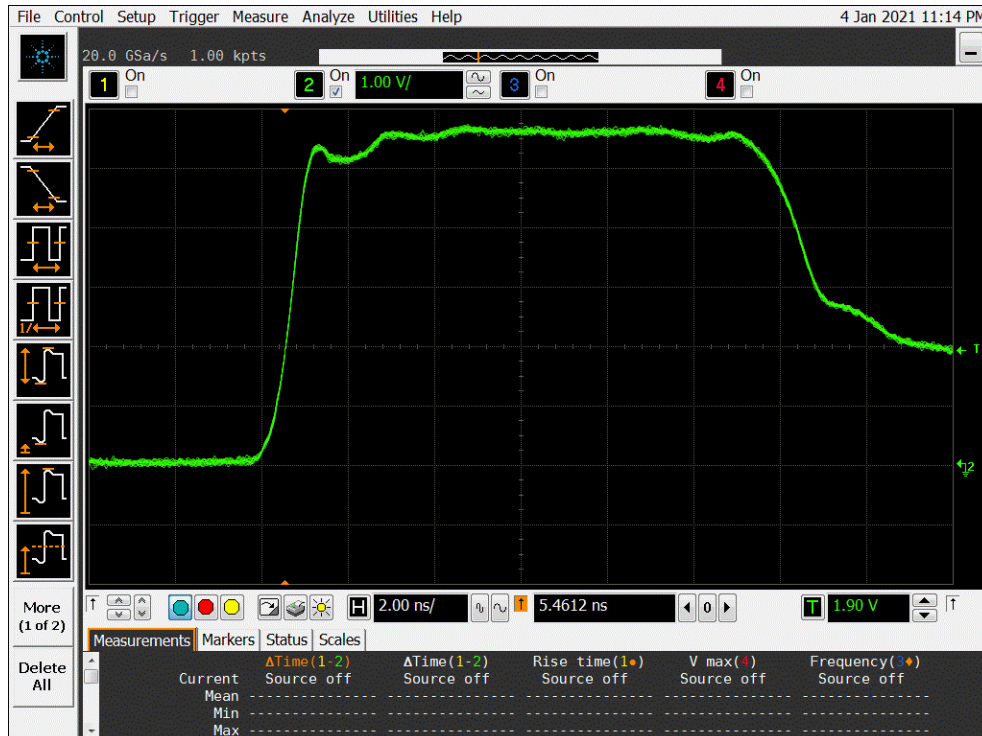


Figure 9b DUT 13298 Post-Annealing Rising Edge



Figure 10a DUT 13304 Pre-Irradiation Rising Edge

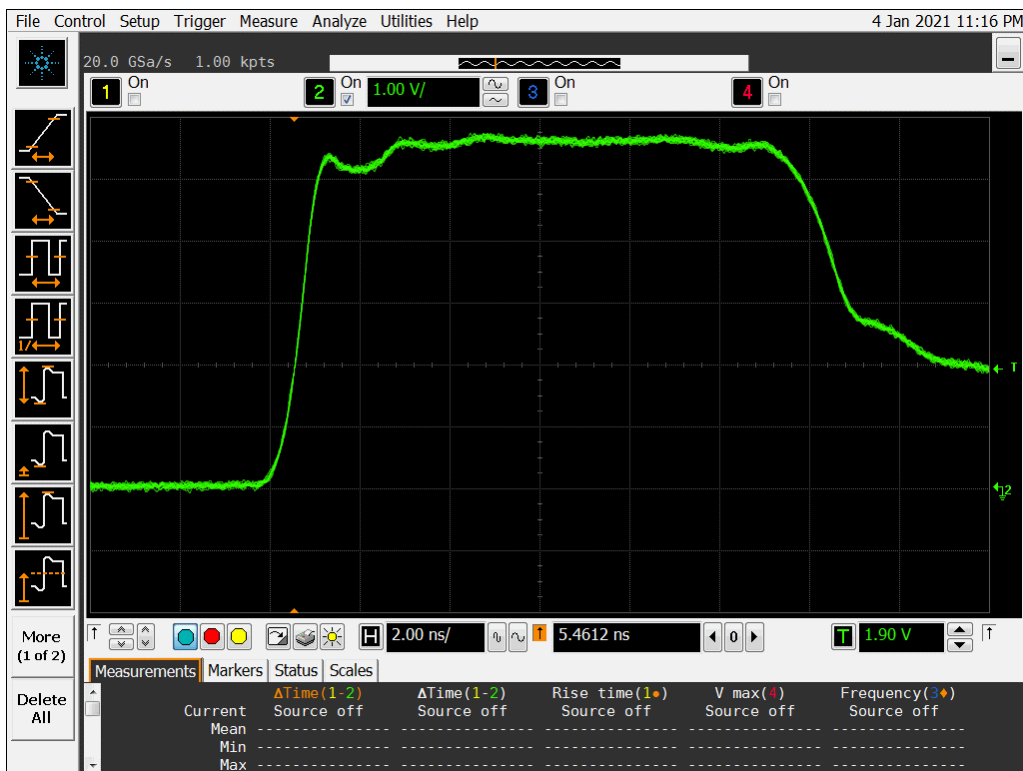


Figure 10b DUT 13304 Post-Annealing Rising Edge

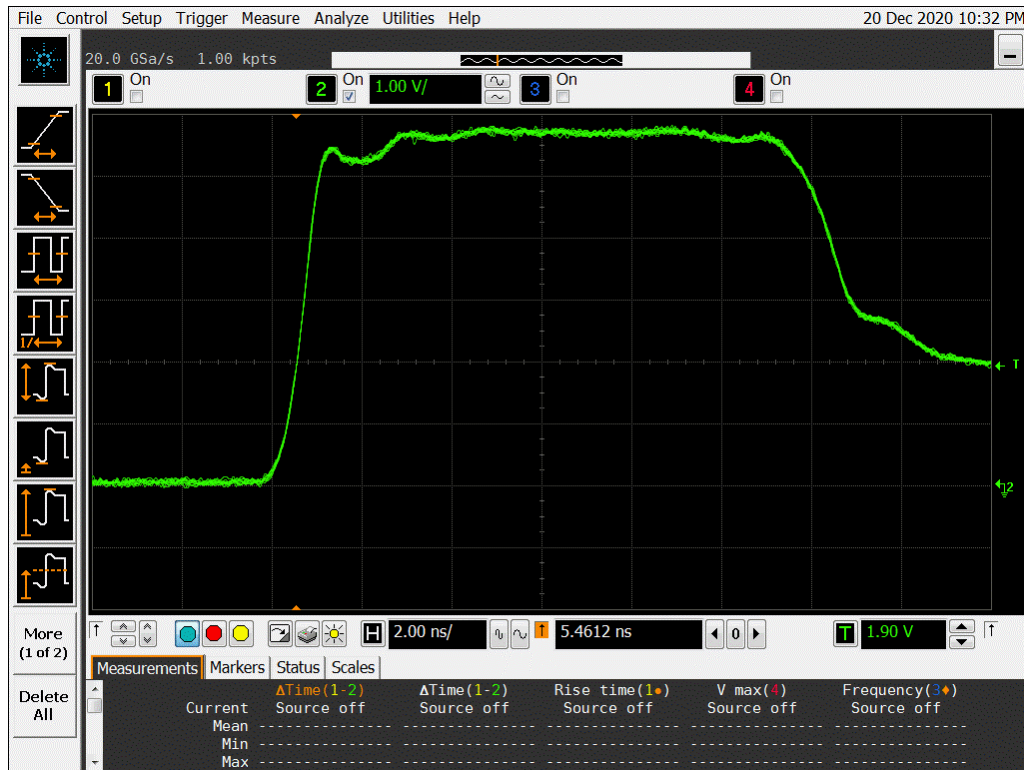
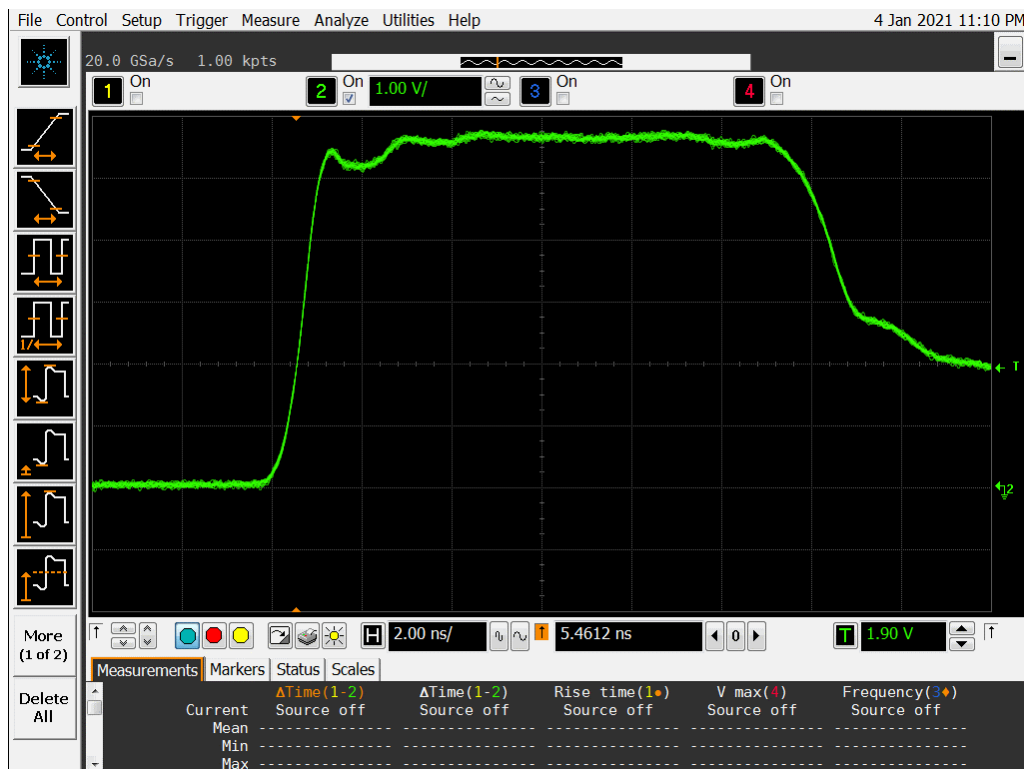

Figure 11a DUT 13273 Pre-Radiation Rising Edge

Figure 11b DUT 13273 Post-Annealing Rising edge



Figure 12a DUT 13280 Pre-Irradiation Rising Edge

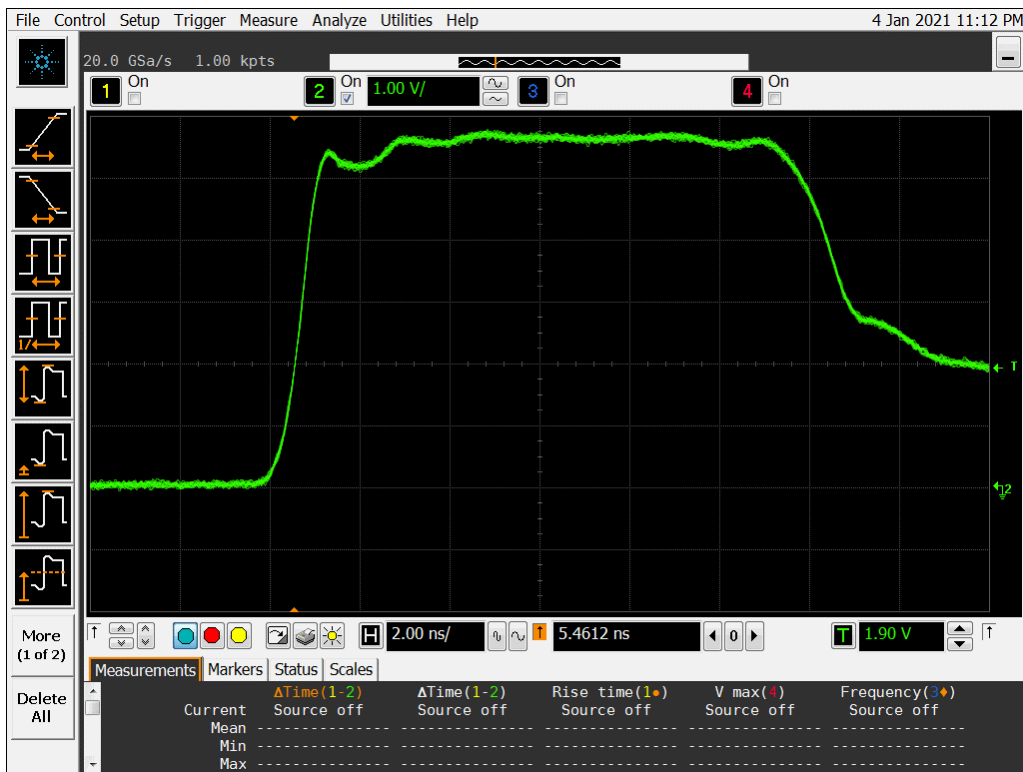


Figure 12b DUT 13280 Post-Annealing Rising Edge



Figure 13a DUT 13260 Pre-Irradiation Rising Edge

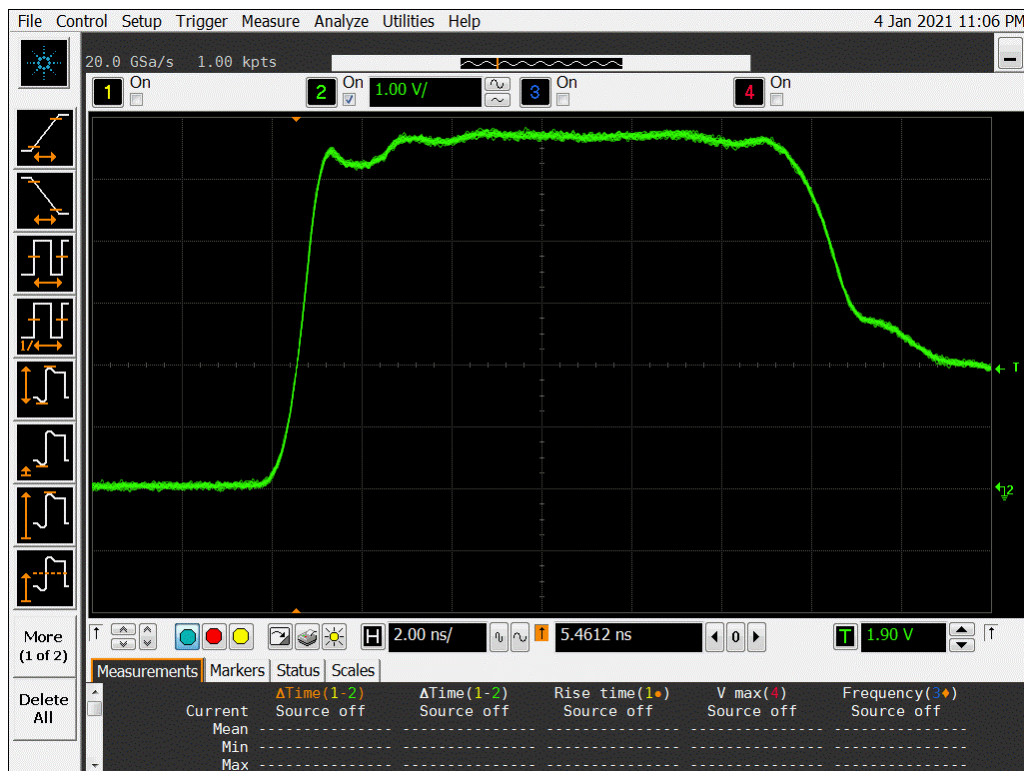


Figure 13b DUT 13260 Post-Annealing Rising Edge



Figure 14a DUT 13267 Pre-Irradiation Rising Edge

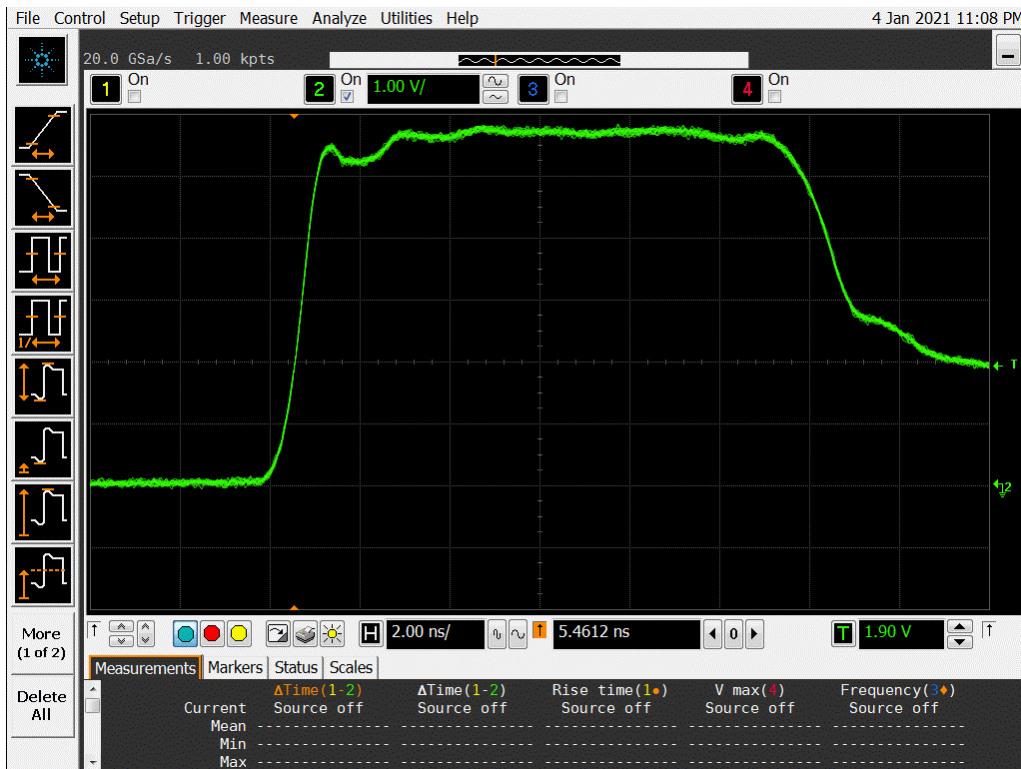


Figure 14b DUT 13267 Post-Annealing Rising Edge

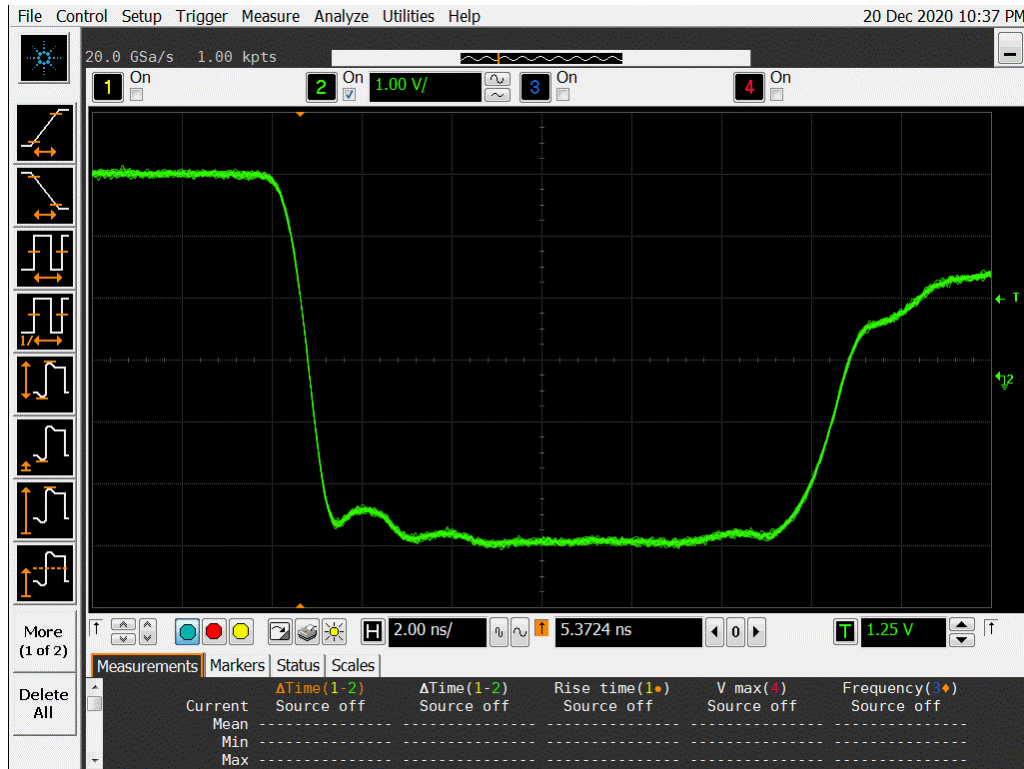


Figure 15a DUT 13298 Pre-Radiation Falling Edge

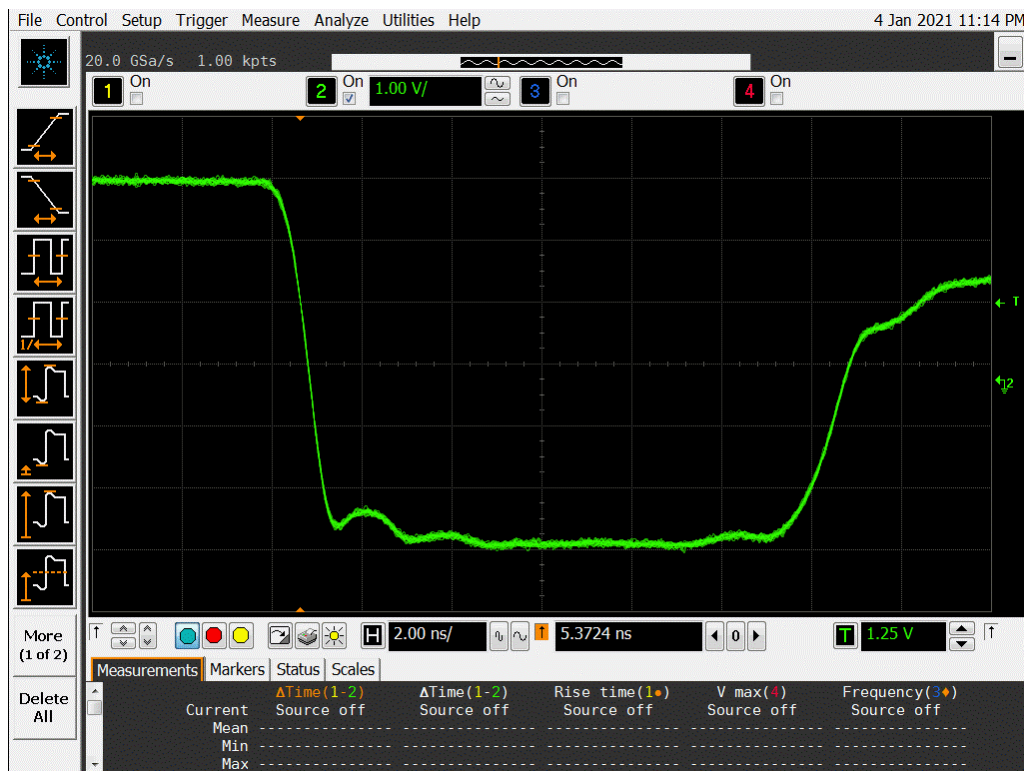


Figure 15b DUT 13298 Post-Annealing Falling Edge

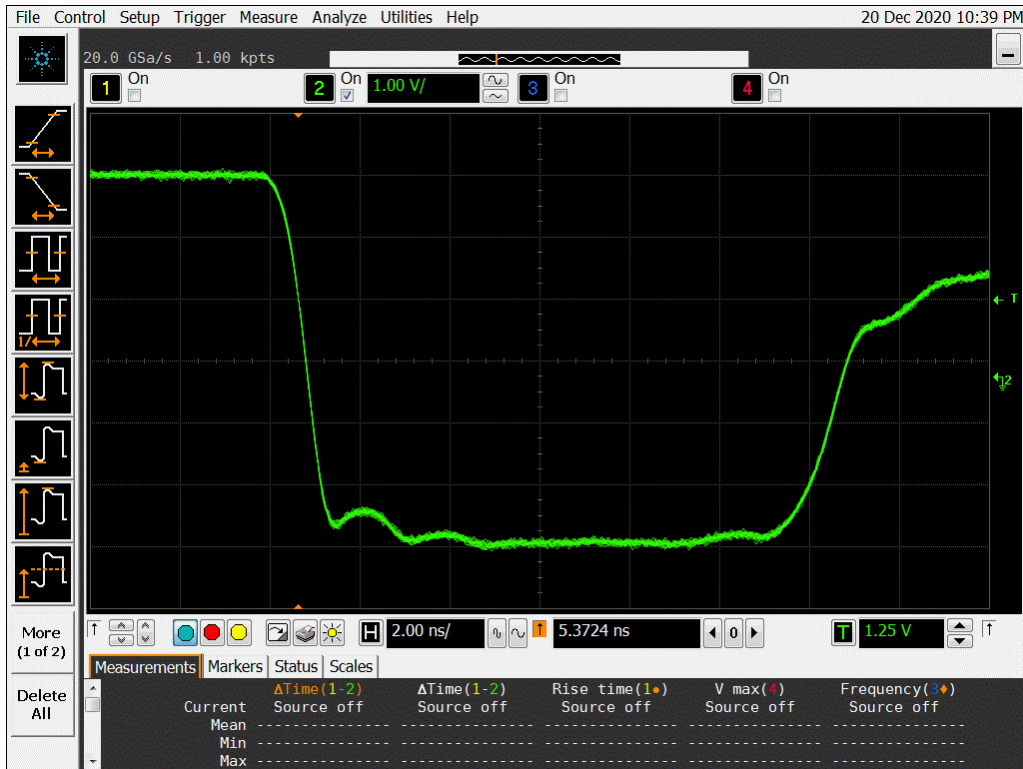


Figure 16a DUT 13304 Pre-Irradiation Falling Edge

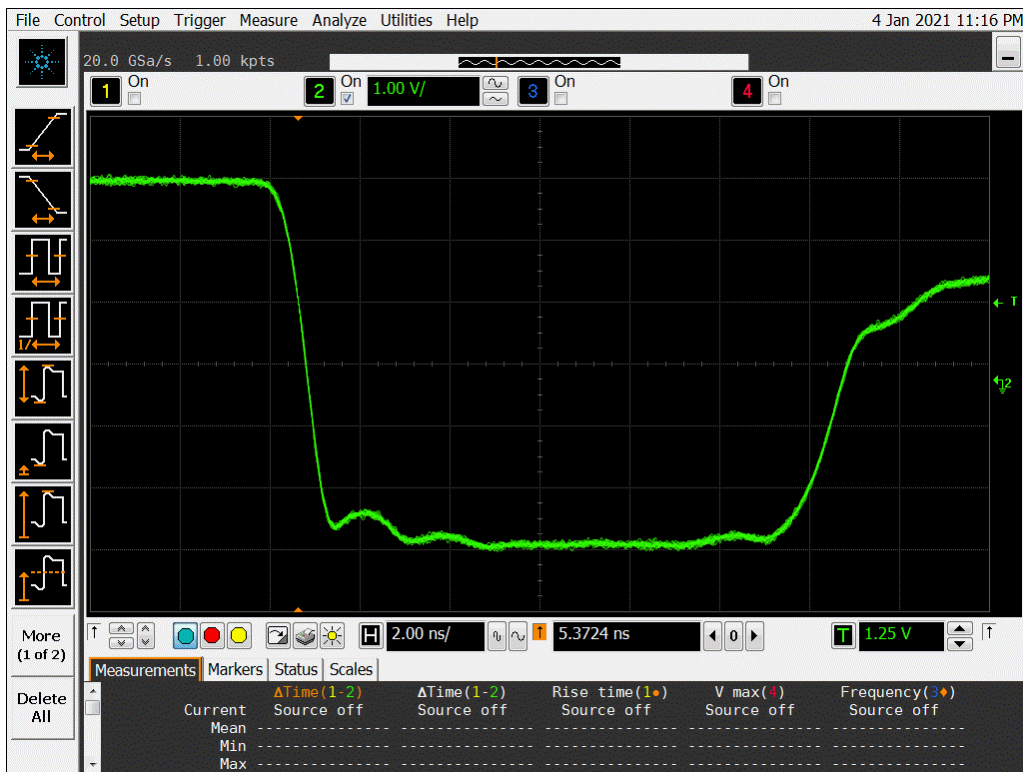


Figure 16b DUT 13304 Post-Annealing Falling Edge

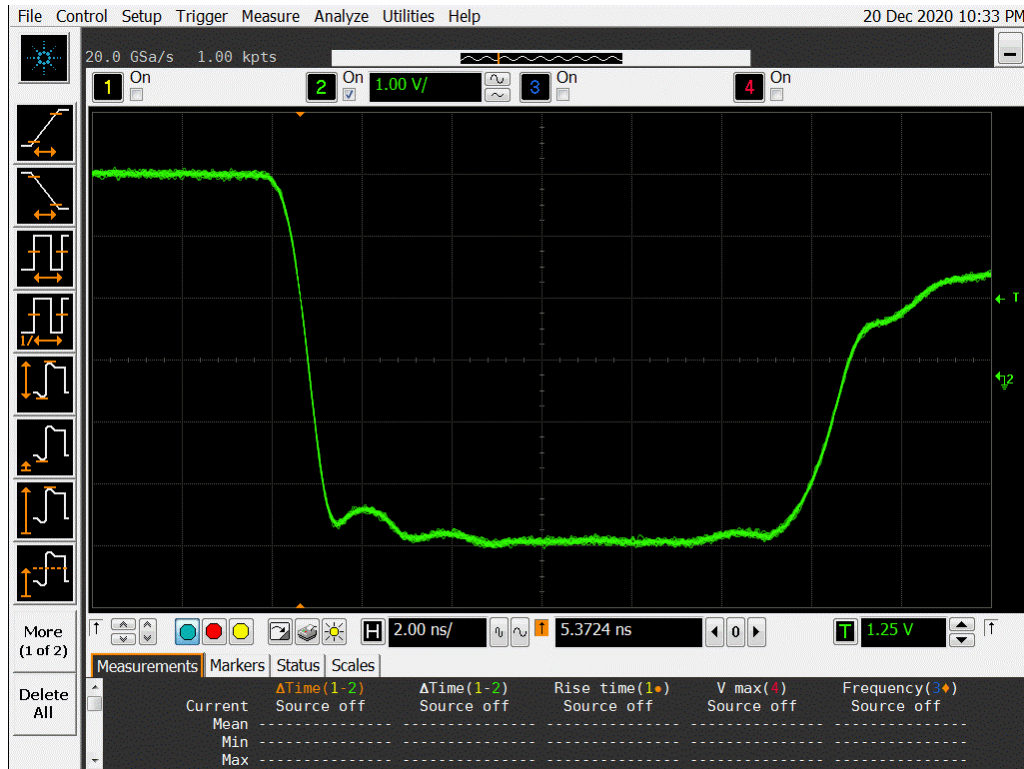


Figure 17a DUT 13273 Pre-Irradiation Falling Edge

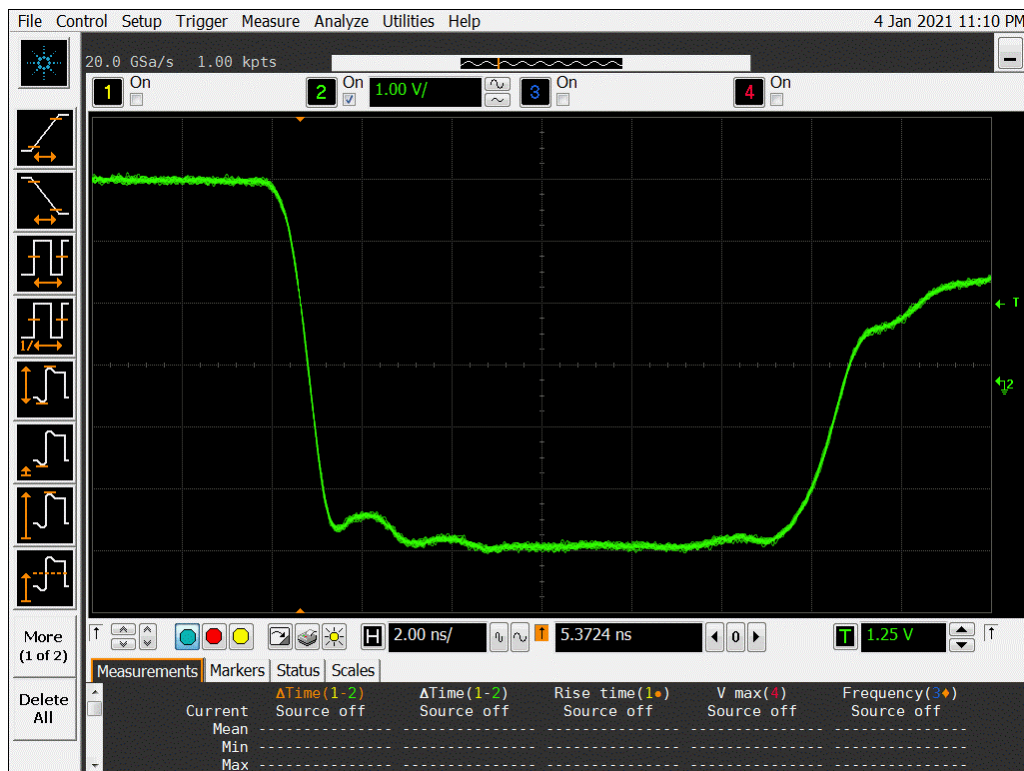
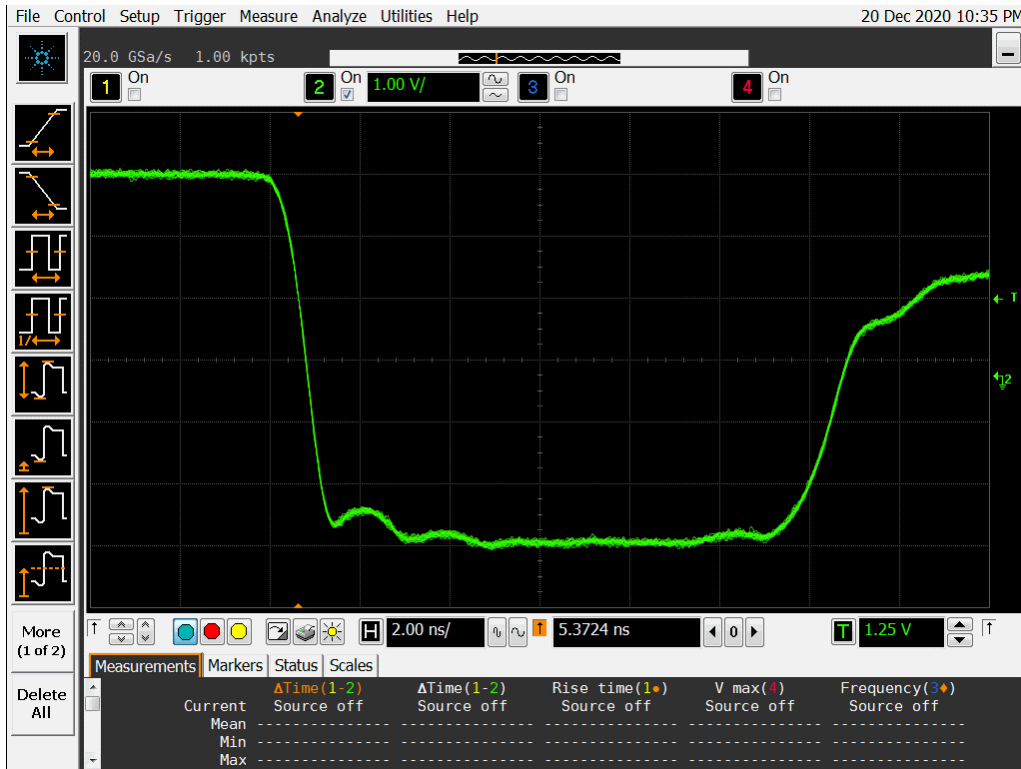
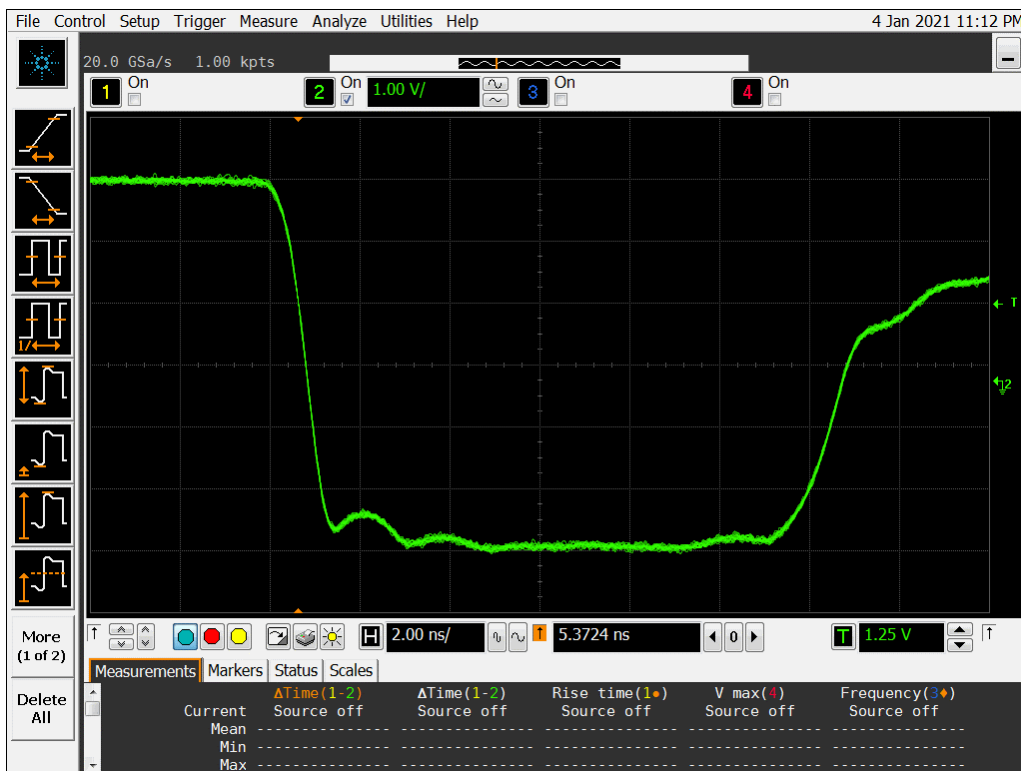


Figure 17b DUT 13273 Post-Annealing Falling Edge


Figure 18a DUT 13280 Pre-Irradiation Falling Edge

Figure 18b DUT 13280 Post-Annealing Falling Edge

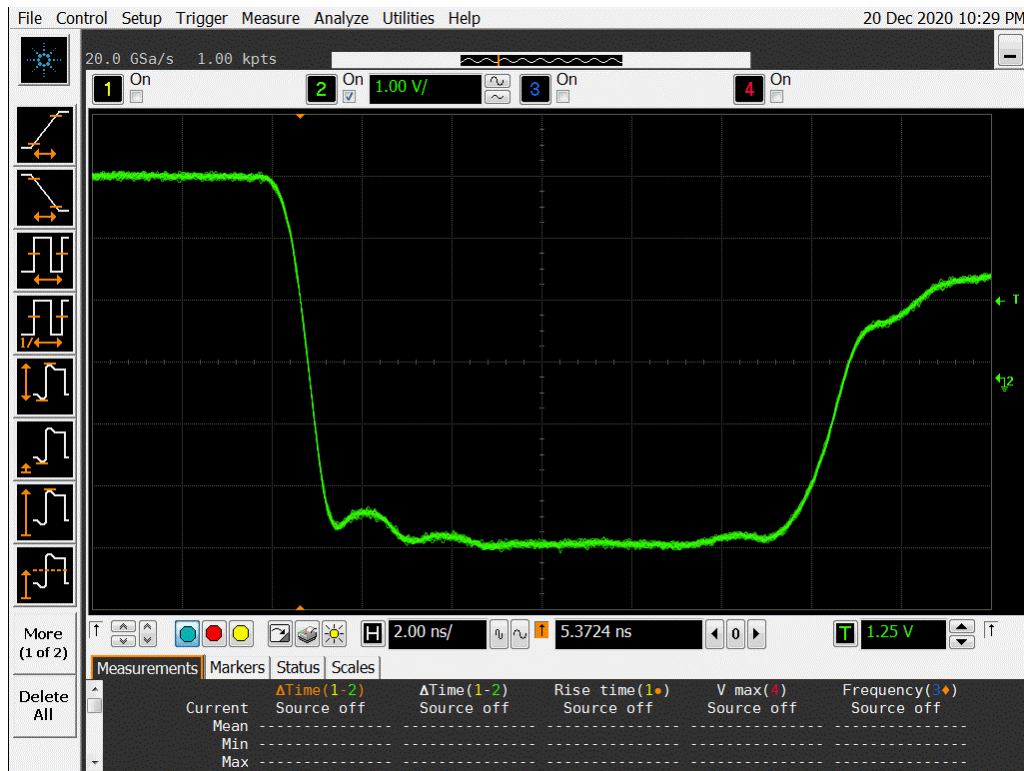


Figure 19a DUT 13260 Pre-Irradiation Falling Edge

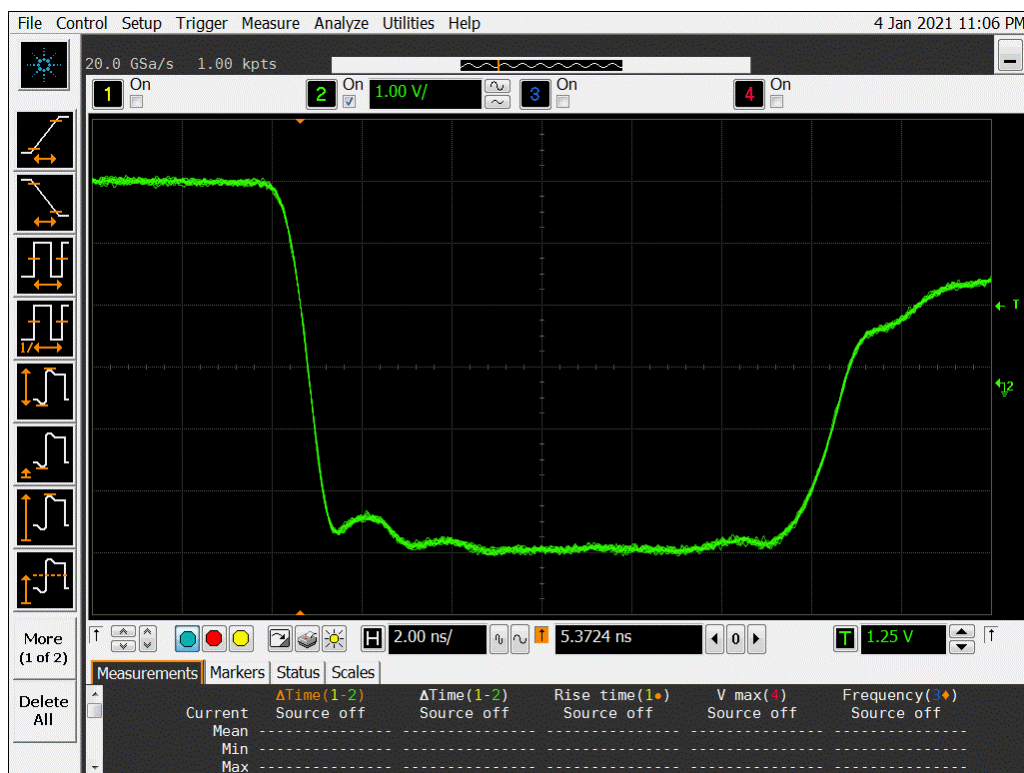


Figure 19b DUT 13260 Post-Annealing Falling Edge

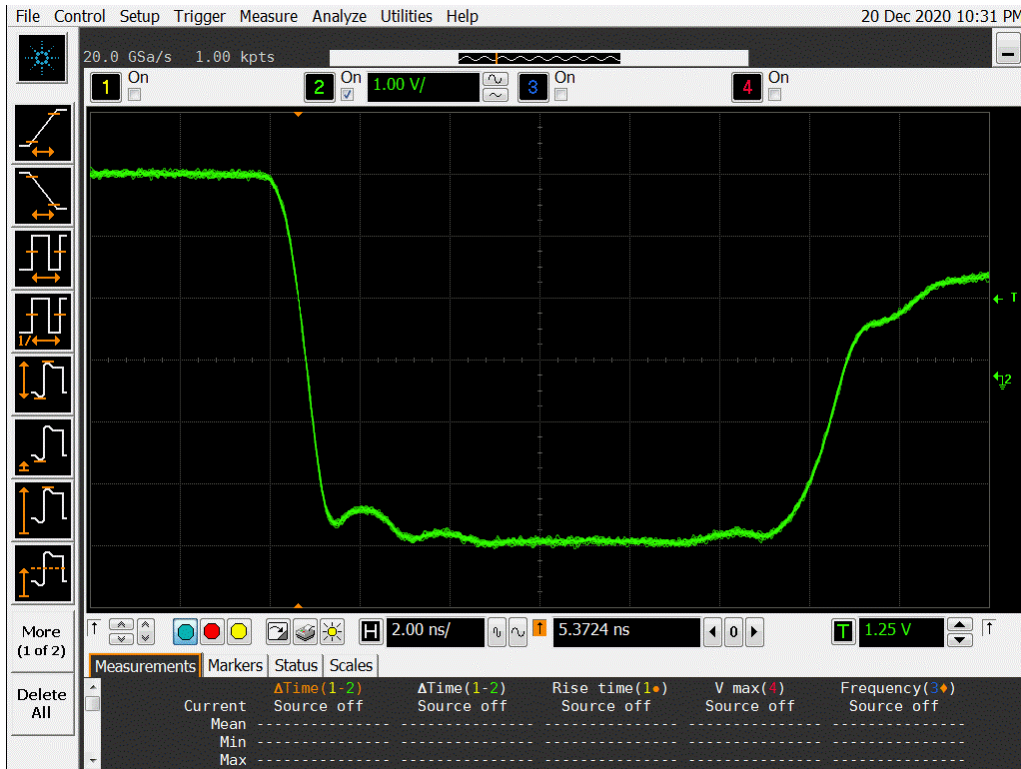


Figure 20a DUT 13267 Pre-Irradiation Falling Edge

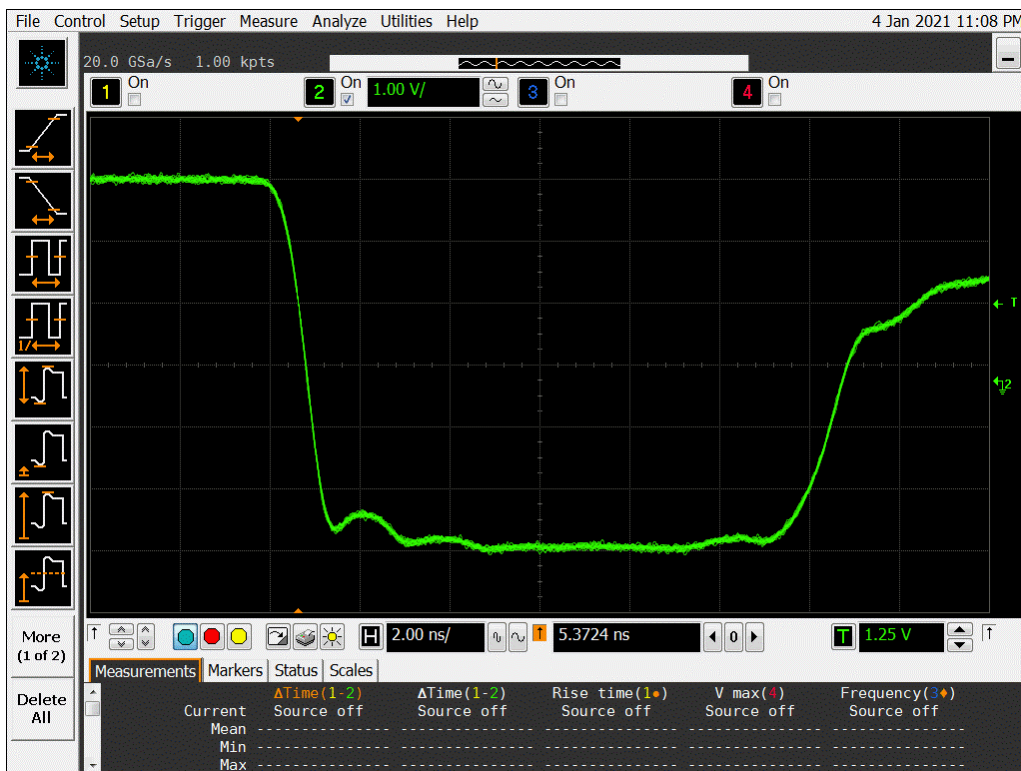


Figure 20b DUT 13267 Post-Annealing Falling Edge

Appendix A: DUT Bias

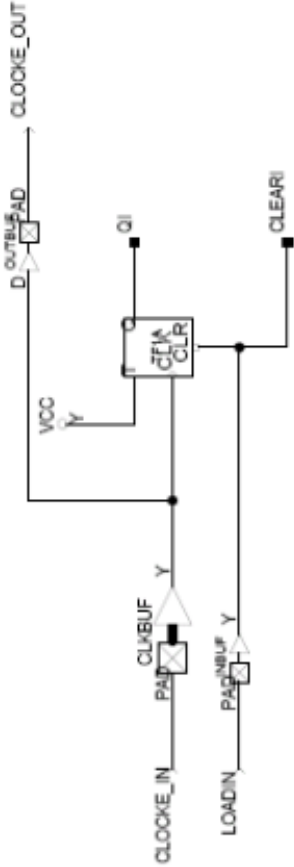


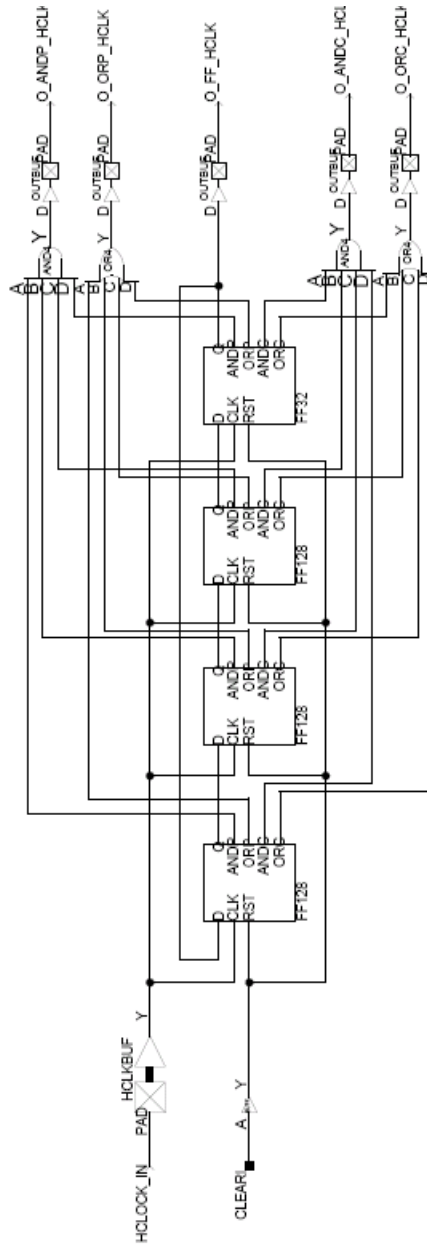
Figure A1 I/O Bias During Irradiation

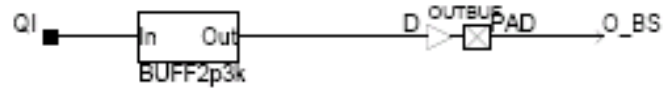


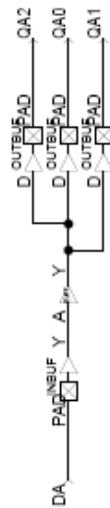
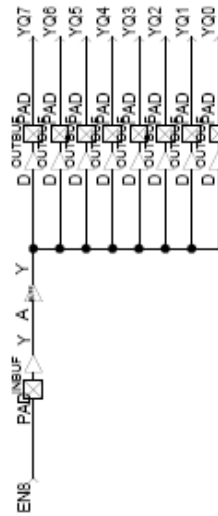
Figure A2 Power Supply, Ground and Special Pins Bias During Irradiation

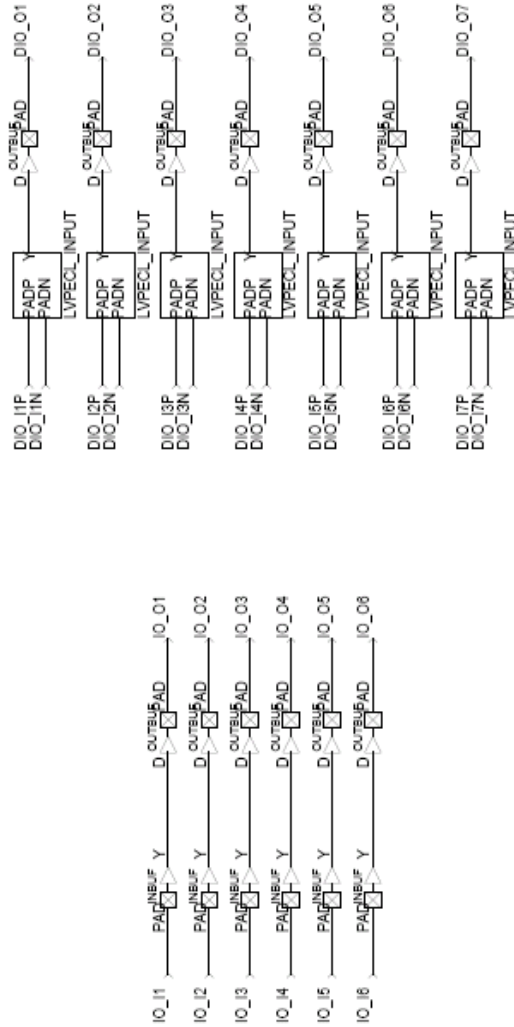
Appendix B: DUT Design Schematics and Verilog Files

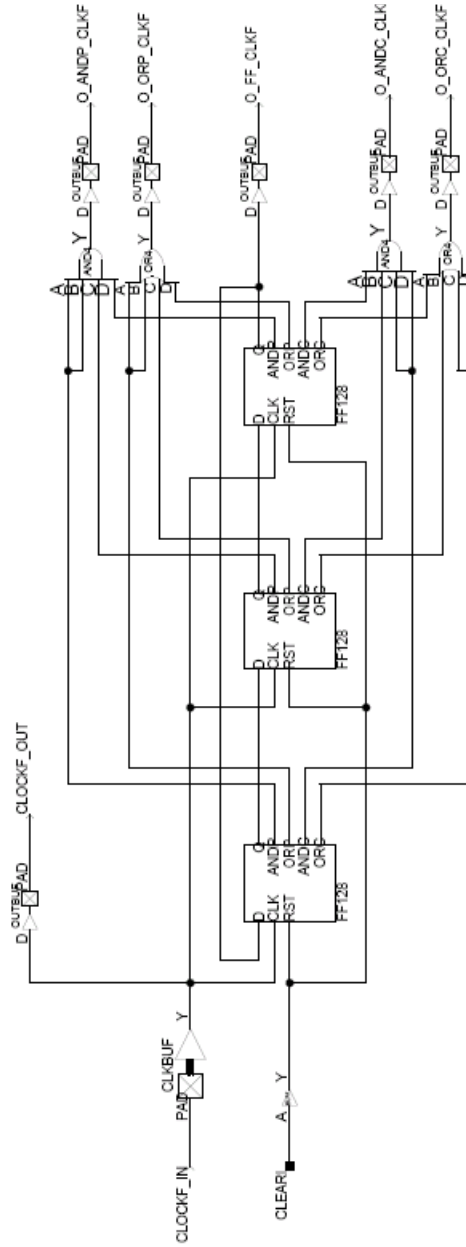


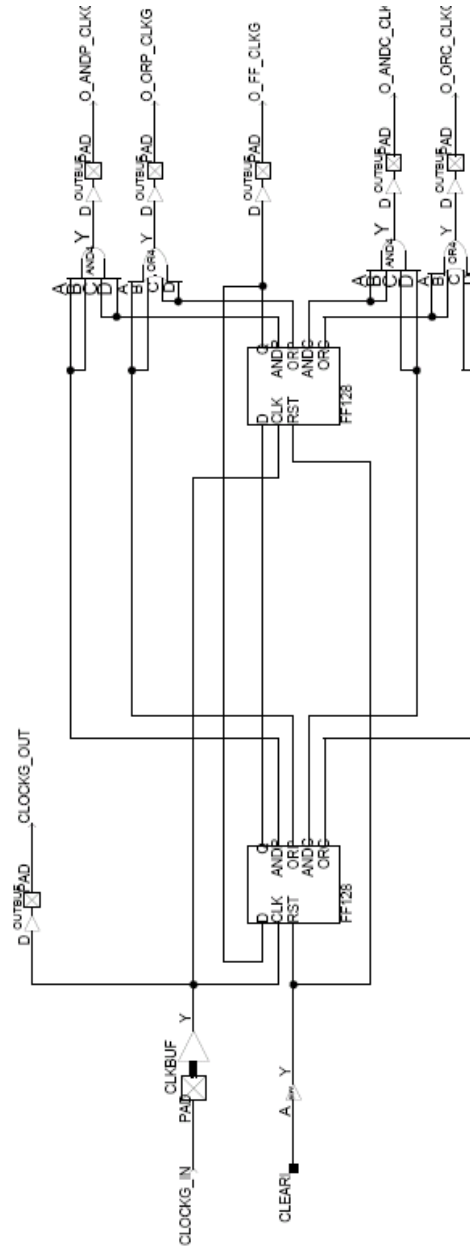


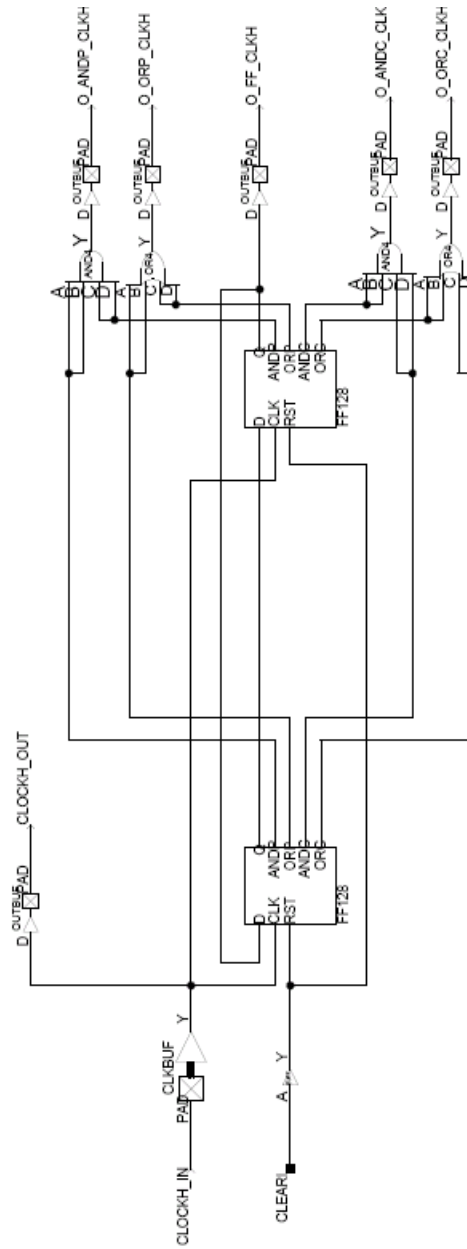












```
// BUFF2p3k.v
`timescale 1 ns/100ps

module BUFF2p3k(In, Out);

input In;

output Out;

wire x1/*synthesis syn_keep=1 lspreserve=1*/;
wire x2/*synthesis syn_keep=1 lspreserve=1*/;
wire x3/*synthesis syn_keep=1 lspreserve=1*/;
wire x4/*synthesis syn_keep=1 lspreserve=1*/;
wire x5/*synthesis syn_keep=1 lspreserve=1*/;
wire x6/*synthesis syn_keep=1 lspreserve=1*/;
wire x7/*synthesis syn_keep=1 lspreserve=1*/;

BUFF1k buff1k_1(.In(In), .Out(x1));
BUFF1k buff1k_2(.In(x1), .Out(x2));
BUFF50 buff3(.In(x2), .Out(x3));
BUFF50 buff4(.In(x3), .Out(x4));
BUFF50 buff5(.In(x4), .Out(x5));
BUFF50 buff6(.In(x5), .Out(x6));
BUFF50 buff7(.In(x6), .Out(x7));
BUFF50 buff8(.In(x7), .Out(Out));

endmodule

// BUFF1k
`timescale 1 ns/100ps

module BUFF1k(In, Out);

input In;

output Out;

wire x1/*synthesis syn_keep=1 lspreserve=1*/;
wire x2/*synthesis syn_keep=1 lspreserve=1*/;
wire x3/*synthesis syn_keep=1 lspreserve=1*/;
wire x4/*synthesis syn_keep=1 lspreserve=1*/;
wire x5/*synthesis syn_keep=1 lspreserve=1*/;
wire x6/*synthesis syn_keep=1 lspreserve=1*/;
wire x7/*synthesis syn_keep=1 lspreserve=1*/;
wire x8/*synthesis syn_keep=1 lspreserve=1*/;
wire x9/*synthesis syn_keep=1 lspreserve=1*/;
wire x10/*synthesis syn_keep=1 lspreserve=1*/;
wire x11/*synthesis syn_keep=1 lspreserve=1*/;
wire x12/*synthesis syn_keep=1 lspreserve=1*/;
wire x13/*synthesis syn_keep=1 lspreserve=1*/;
wire x14/*synthesis syn_keep=1 lspreserve=1*/;
wire x15/*synthesis syn_keep=1 lspreserve=1*/;
wire x16/*synthesis syn_keep=1 lspreserve=1*/;
wire x17/*synthesis syn_keep=1 lspreserve=1*/;
wire x18/*synthesis syn_keep=1 lspreserve=1*/;
wire x19/*synthesis syn_keep=1 lspreserve=1*/;
```

```
BUFF50 buff1 (.In(In), .Out(x1));
BUFF50 buff2 (.In(x1), .Out(x2));
BUFF50 buff3 (.In(x2), .Out(x3));
BUFF50 buff4 (.In(x3), .Out(x4));
BUFF50 buff5 (.In(x4), .Out(x5));
BUFF50 buff6 (.In(x5), .Out(x6));
BUFF50 buff7 (.In(x6), .Out(x7));
BUFF50 buff8 (.In(x7), .Out(x8));
BUFF50 buff9 (.In(x8), .Out(x9));
BUFF50 buff10 (.In(x9), .Out(x10));
```

```
BUFF50 buff11 (.In(x10), .Out(x11));
BUFF50 buff12 (.In(x11), .Out(x12));
BUFF50 buff13 (.In(x12), .Out(x13));
BUFF50 buff14 (.In(x13), .Out(x14));
BUFF50 buff15 (.In(x14), .Out(x15));
BUFF50 buff16 (.In(x15), .Out(x16));
BUFF50 buff17 (.In(x16), .Out(x17));
BUFF50 buff18 (.In(x17), .Out(x18));
BUFF50 buff19 (.In(x18), .Out(x19));
BUFF50 buff20 (.In(x19), .Out(Out));
```

```
endmodule
```

```
// BUFF50
```

```
`timescale 1 ns/100ps
```

```
module BUFF50 (In, Out);
```

```
input In;
```

```
output Out;
```

```
wire x1 /*synthesis syn_keep=1 alspreserve=1*/;
wire x2 /*synthesis syn_keep=1 alspreserve=1*/;
wire x3 /*synthesis syn_keep=1 alspreserve=1*/;
wire x4 /*synthesis syn_keep=1 alspreserve=1*/;
wire x5 /*synthesis syn_keep=1 alspreserve=1*/;
wire x6 /*synthesis syn_keep=1 alspreserve=1*/;
wire x7 /*synthesis syn_keep=1 alspreserve=1*/;
wire x8 /*synthesis syn_keep=1 alspreserve=1*/;
wire x9 /*synthesis syn_keep=1 alspreserve=1*/;
wire x10 /*synthesis syn_keep=1 alspreserve=1*/;
wire x11 /*synthesis syn_keep=1 alspreserve=1*/;
wire x12 /*synthesis syn_keep=1 alspreserve=1*/;
wire x13 /*synthesis syn_keep=1 alspreserve=1*/;
wire x14 /*synthesis syn_keep=1 alspreserve=1*/;
wire x15 /*synthesis syn_keep=1 alspreserve=1*/;
wire x16 /*synthesis syn_keep=1 alspreserve=1*/;
wire x17 /*synthesis syn_keep=1 alspreserve=1*/;
wire x18 /*synthesis syn_keep=1 alspreserve=1*/;
wire x19 /*synthesis syn_keep=1 alspreserve=1*/;
wire x20 /*synthesis syn_keep=1 alspreserve=1*/;
wire x21 /*synthesis syn_keep=1 alspreserve=1*/;
wire x22 /*synthesis syn_keep=1 alspreserve=1*/;
```

```
wire x23/*synthesis syn_keep=1 alspreserve=1*/;  
wire x24/*synthesis syn_keep=1 alspreserve=1*/;  
wire x25/*synthesis syn_keep=1 alspreserve=1*/;  
wire x26/*synthesis syn_keep=1 alspreserve=1*/;  
wire x27/*synthesis syn_keep=1 alspreserve=1*/;  
wire x28/*synthesis syn_keep=1 alspreserve=1*/;  
wire x29/*synthesis syn_keep=1 alspreserve=1*/;  
wire x30/*synthesis syn_keep=1 alspreserve=1*/;  
wire x31/*synthesis syn_keep=1 alspreserve=1*/;  
wire x32/*synthesis syn_keep=1 alspreserve=1*/;  
wire x33/*synthesis syn_keep=1 alspreserve=1*/;  
wire x34/*synthesis syn_keep=1 alspreserve=1*/;  
wire x35/*synthesis syn_keep=1 alspreserve=1*/;  
wire x36/*synthesis syn_keep=1 alspreserve=1*/;  
wire x37/*synthesis syn_keep=1 alspreserve=1*/;  
wire x38/*synthesis syn_keep=1 alspreserve=1*/;  
wire x39/*synthesis syn_keep=1 alspreserve=1*/;  
wire x40/*synthesis syn_keep=1 alspreserve=1*/;  
wire x41/*synthesis syn_keep=1 alspreserve=1*/;  
wire x42/*synthesis syn_keep=1 alspreserve=1*/;  
wire x43/*synthesis syn_keep=1 alspreserve=1*/;  
wire x44/*synthesis syn_keep=1 alspreserve=1*/;  
wire x45/*synthesis syn_keep=1 alspreserve=1*/;  
wire x46/*synthesis syn_keep=1 alspreserve=1*/;  
wire x47/*synthesis syn_keep=1 alspreserve=1*/;  
wire x48/*synthesis syn_keep=1 alspreserve=1*/;  
wire x49/*synthesis syn_keep=1 alspreserve=1*/;
```

```
BUFF buff1 (.A(In), .Y(x1));  
BUFF buff2 (.A(x1), .Y(x2));  
BUFF buff3 (.A(x2), .Y(x3));  
BUFF buff4 (.A(x3), .Y(x4));  
BUFF buff5 (.A(x4), .Y(x5));  
BUFF buff6 (.A(x5), .Y(x6));  
BUFF buff7 (.A(x6), .Y(x7));  
BUFF buff8 (.A(x7), .Y(x8));  
BUFF buff9 (.A(x8), .Y(x9));  
BUFF buff10 (.A(x9), .Y(x10));
```

```
BUFF buff11 (.A(x10), .Y(x11));  
BUFF buff12 (.A(x11), .Y(x12));  
BUFF buff13 (.A(x12), .Y(x13));  
BUFF buff14 (.A(x13), .Y(x14));  
BUFF buff15 (.A(x14), .Y(x15));  
BUFF buff16 (.A(x15), .Y(x16));  
BUFF buff17 (.A(x16), .Y(x17));  
BUFF buff18 (.A(x17), .Y(x18));  
BUFF buff19 (.A(x18), .Y(x19));  
BUFF buff20 (.A(x19), .Y(x20));
```

```
BUFF buff21 (.A(x20), .Y(x21));  
BUFF buff22 (.A(x21), .Y(x22));  
BUFF buff23 (.A(x22), .Y(x23));  
BUFF buff24 (.A(x23), .Y(x24));  
BUFF buff25 (.A(x24), .Y(x25));  
BUFF buff26 (.A(x25), .Y(x26));
```

```
BUFFbuff27 (.A(x26), .Y(x27));  
BUFFbuff28 (.A(x27), .Y(x28));  
BUFFbuff29 (.A(x28), .Y(x29));  
BUFFbuff30 (.A(x29), .Y(x30));
```

```
BUFFbuff31 (.A(x30), .Y(x31));  
BUFFbuff32 (.A(x31), .Y(x32));  
BUFFbuff33 (.A(x32), .Y(x33));  
BUFFbuff34 (.A(x33), .Y(x34));  
BUFFbuff35 (.A(x34), .Y(x35));  
BUFFbuff36 (.A(x35), .Y(x36));  
BUFFbuff37 (.A(x36), .Y(x37));  
BUFFbuff38 (.A(x37), .Y(x38));  
BUFFbuff39 (.A(x38), .Y(x39));  
BUFFbuff40 (.A(x39), .Y(x40));
```

```
BUFFbuff41 (.A(x40), .Y(x41));  
BUFFbuff42 (.A(x41), .Y(x42));  
BUFFbuff43 (.A(x42), .Y(x43));  
BUFFbuff44 (.A(x43), .Y(x44));  
BUFFbuff45 (.A(x44), .Y(x45));  
BUFFbuff46 (.A(x45), .Y(x46));  
BUFFbuff47 (.A(x46), .Y(x47));  
BUFFbuff48 (.A(x47), .Y(x48));  
BUFFbuff49 (.A(x48), .Y(x49));  
BUFFbuff50 (.A(x49), .Y(Out));
```

```
endmodule
```

```
// FF128  
`timescale 1 ns/100ps  
module FF128 (D, Q, CLK, RST, ANDP, ORP, ANDC, ORC);
```

```
input D, CLK, RST;  
output Q, ANDP, ORP, ANDC, ORC;
```

```
wire x1, x2, x3, Q;  
wire andp_a, andp_b, andp_c, andp_d, orp_a, orp_b, orp_c, orp_d;  
wire andc_a, andc_b, andc_c, andc_d, orc_a, orc_b, orc_c, orc_d;
```

```
FF32 dff_a(.D(D), .Q(x1), .CLK(CLK), .RST(RST), .ANDP(andp_a), .ORP(orp_a),  
.ANDC(andc_a), .ORC(orc_a));
```

```
FF32 dff_b(.D(x1), .Q(x2), .CLK(CLK), .RST(RST), .ANDP(andp_b), .ORP(orp_b),  
.ANDC(andc_b), .ORC(orc_b));
```

```
FF32 dff_c(.D(x2), .Q(x3), .CLK(CLK), .RST(RST), .ANDP(andp_c), .ORP(orp_c),  
.ANDC(andc_c), .ORC(orc_c));
```

```
FF32 dff_d(.D(x3), .Q(Q), .CLK(CLK), .RST(RST), .ANDP(andp_d), .ORP(orp_d),  
.ANDC(andc_d), .ORC(orc_d));
```

```
AND4 and4p (.A(andp_a), .B(andp_b), .C(andp_c), .D(andp_d), .Y(ANDP));  
OR4 or4p (.A(orp_a), .B(orp_b), .C(orp_c), .D(orp_d), .Y(ORP));
```

```
AND4 and4c (.A(andc_a), .B(andc_b), .C(andc_c), .D(andc_d), .Y(ANDC));
```



```
OR4 or4c (.A(orc_a),.B(orc_b),.C(orc_c),.D(orc_d),.Y(ORC));

endmodule

// FF32
`timescale 1 ns/100ps
module FF32(D,Q,CLK,RST,ANDP,ORP,ANDC,ORC);

input D,CLK,RST;
output Q,ANDP,ORP,ANDC,ORC;

wire x1,x2,x3,Q;
wire andp_a,andp_b,andp_c,andp_d,orp_a,orp_b,orp_c,orp_d;
wire andc_a,andc_b,andc_c,andc_d,orc_a,orc_b,orc_c,orc_d;

FF8 dff_a(.D(D),.Q(x1),.CLK(CLK),.RST(RST),.ANDP(andp_a),.ORP(orp_a),
.ANDC(andc_a),.ORC(orc_a));

FF8 dff_b(.D(x1),.Q(x2),.CLK(CLK),.RST(RST),.ANDP(andp_b),.ORP(orp_b),
.ANDC(andc_b),.ORC(orc_b));

FF8 dff_c(.D(x2),.Q(x3),.CLK(CLK),.RST(RST),.ANDP(andp_c),.ORP(orp_c),
.ANDC(andc_c),.ORC(orc_c));

FF8 dff_d(.D(x3),.Q(Q),.CLK(CLK),.RST(RST),.ANDP(andp_d),.ORP(orp_d),
.ANDC(andc_d),.ORC(orc_d));

AND4 and4p(.A(andp_a),.B(andp_b),.C(andp_c),.D(andp_d),.Y(ANDP));
OR4 or4p(.A(orp_a),.B(orp_b),.C(orp_c),.D(orp_d),.Y(ORP));

AND4 and4c(.A(andc_a),.B(andc_b),.C(andc_c),.D(andc_d),.Y(ANDC));
OR4 or4c(.A(orc_a),.B(orc_b),.C(orc_c),.D(orc_d),.Y(ORC));

endmodule

// FF8
`timescale 1 ns/100ps

module FF8(D,Q,CLK,RST,ANDP,ORP,ANDC,ORC);

input D,CLK,RST;
output Q,ANDP,ORP,ANDC,ORC;

wire x1,x2,x3,x4,x5,x6,x7;

DFC1B dff1(.D(D),.Q(x1),.CLK(CLK),.CLR(RST));
DFP1B dff2(.D(x1),.Q(x2),.CLK(CLK),.PRE(RST));
DFC1B dff3(.D(x2),.Q(x3),.CLK(CLK),.CLR(RST));
DFP1B dff4(.D(x3),.Q(x4),.CLK(CLK),.PRE(RST));
DFC1B dff5(.D(x4),.Q(x5),.CLK(CLK),.CLR(RST));
DFP1B dff6(.D(x5),.Q(x6),.CLK(CLK),.PRE(RST));
DFC1B dff7(.D(x6),.Q(x7),.CLK(CLK),.CLR(RST));
DFP1B dff8(.D(x7),.Q(Q),.CLK(CLK),.PRE(RST));

AND4 and4p(.A(x2),.B(x4),.C(x6),.D(Q),.Y(ANDP));
OR4 or4p(.A(x2),.B(x4),.C(x6),.D(Q),.Y(ORP));
```

```

AND4 and4c (.A(x1), .B(x3), .C(x5), .D(x7), .Y(ANDC));
OR4 or4c (.A(x1), .B(x3), .C(x5), .D(x7), .Y(ORC));

endmodule

//Top_RAM_Module.v
`timescale 1 ns/100ps

module Top_RAM_Module(Psel0, Psel1, RC_en, RC_clr, RC_clk, Write, Read, Wclk, Rclk,
    Q_RAM);
input Psel0, Psel1, RC_en, RC_clr, RC_clk, Write, Read, Wclk, Rclk;
output [5:0] Q_RAM;

wire Gnd, Vcc;
wire mx0, mx1;
wire [12:0] rc;
wire [3:0] dec;
wire y_0w, y_0r, y_1w, y_1r, y_2w, y_2r, y_3w, y_3r;
// y_4w, y_4r, y_5w, y_5r, y_6w, y_6r, y_7w, y_7r;
wire [5:0] DIN;
wire [5:0] Q_b0;
wire [5:0] Q_b1;
wire [5:0] Q_b2;
wire [5:0] Q_b3;
//wire [5:0] Q_b4;
//wire [5:0] Q_b5;
//wire [5:0] Q_b6;
//wire [5:0] Q_b7;

GND gnd_0(.Y(Gnd));
VCC vcc_0(.Y(Vcc));

mux_2x1 mux_0(.Data0_port(Gnd), .Data1_port(Vcc), .Sel0(Psel0), .Result(mx0));
mux_2x1 mux_1(.Data0_port(Gnd), .Data1_port(Vcc), .Sel0(Psel1), .Result(mx1));

counter_13 counter_0(.Enable(RC_en), .Aclr(RC_clr), .Clock(RC_clk), .Q(rc));

decoder_2to4 decoder_0(.Data0(rc[11]), .Data1(rc[12]), .Eq(dec));

NAND2 nand_0w(.A(dec[0]), .B(Write), .Y(y_0w));
NAND2 nand_0r(.A(dec[0]), .B(Read), .Y(y_0r));

ram_2048x6 ram_blk0(.Data(DIN), .Q(Q_b0), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_0w), .RE(y_0r), .WClock(Wclk), .RClock(Rclk));

assign DIN[0]=mx0, DIN[1]=mx1, DIN[2]=mx0, DIN[3]=mx1, DIN[4]=mx0, DIN[5]=mx1;

NAND2 nand_1w(.A(dec[1]), .B(Write), .Y(y_1w));
NAND2 nand_1r(.A(dec[1]), .B(Read), .Y(y_1r));

ram_2048x6 ram_blk1(.Data(DIN), .Q(Q_b1), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_1w), .RE(y_1r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_2w(.A(dec[2]), .B(Write), .Y(y_2w));
NAND2 nand_2r(.A(dec[2]), .B(Read), .Y(y_2r));

```

```
ram_2048x6 ram_blk2(.Data(DIN),
    .Q(Q_b2), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_2w), .RE(y_2r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_3w(.A(dec[3]), .B(Write), .Y(y_3w));
NAND2 nand_3r(.A(dec[3]), .B(Read), .Y(y_3r));

ram_2048x6 ram_blk3(.Data(DIN),
    .Q(Q_b3), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_3w), .RE(y_3r), .WClock(Wclk), .RClock(Rclk));

/* NAND2 nand_4w(.A(dec[4]), .B(Write), .Y(y_4w));
NAND2 nand_4r(.A(dec[4]), .B(Read), .Y(y_4r));

ram_2048x3 ram_blk4(.Data(DIN),
    .Q(Q_b4), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_4w), .RE(y_4r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_5w(.A(dec[5]), .B(Write), .Y(y_5w));
NAND2 nand_5r(.A(dec[5]), .B(Read), .Y(y_5r));

ram_2048x3 ram_blk5(.Data(DIN),
    .Q(Q_b5), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_5w), .RE(y_5r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_6w(.A(dec[6]), .B(Write), .Y(y_6w));
NAND2 nand_6r(.A(dec[6]), .B(Read), .Y(y_6r));

ram_2048x3 ram_blk6(.Data(DIN),
    .Q(Q_b6), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_6w), .RE(y_6r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_7w(.A(dec[7]), .B(Write), .Y(y_7w));
NAND2 nand_7r(.A(dec[7]), .B(Read), .Y(y_7r));

ram_2048x3 ram_blk7(.Data(DIN),
    .Q(Q_b7), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
    .WE(y_7w), .RE(y_7r), .WClock(Wclk), .RClock(Rclk)); */

mux_6x4 mux_6x4_0(.Data0_port(Q_b0), .Data1_port(Q_b1), .Data2_port(Q_b2),
    .Data3_port(Q_b3), .Sel0(rc[11]),
    .Sel1(rc[12]), .Result(Q_RAM));

endmodule
```

```
`timescale 1 ns/100ps
// Version: 6.0 SP3 6.0.30.3
```

```
module mux_2x1(Data0_port,Data1_port,Sel0,Result);
input Data0_port, Data1_port, Sel0;
output Result;
```

```
    MX2 MX2_Result(.A(Data0_port),.B(Data1_port),.S(Sel0),.Y(
        Result));
```

```
endmodule
```

```
`timescale 1 ns/100ps
// Version: 6.2 SP2 6.2.52.7
```

```
module counter_13(Enable,Aclr,Clock,Q);
input Enable, Aclr, Clock;
output [12:0] Q;
```

```
wire ClrAux_0_net, ClrAux_7_net, MX2_1_Y, MX2_7_Y, MX2_4_Y,
    CM8_0_Y, MX2_10_Y, MX2_9_Y, MX2_3_Y, MX2_5_Y, MX2_6_Y,
    MX2_0_Y, MX2_8_Y, MX2_2_Y, MX2_11_Y, VCC, GND;
```

```
VCC VCC_1_net(.Y(VCC));
GND GND_1_net(.Y(GND));
DFC1D DFC1D_Q_7_inst(.D(MX2_1_Y),.CLK(Q[6]),.CLR(
    ClrAux_7_net),.Q(Q[7]));
DFC1D DFC1D_Q_1_inst(.D(MX2_7_Y),.CLK(Q[0]),.CLR(
    ClrAux_0_net),.Q(Q[1]));
BUFF BUFF_ClrAux_0_inst(.A(Aclr),.Y(ClrAux_0_net));
MX2 MX2_9(.A(VCC),.B(GND),.S(Q[5]),.Y(MX2_9_Y));
DFC1D DFC1D_Q_2_inst(.D(MX2_6_Y),.CLK(Q[1]),.CLR(
    ClrAux_0_net),.Q(Q[2]));
MX2 MX2_0(.A(VCC),.B(GND),.S(Q[8]),.Y(MX2_0_Y));
DFC1D DFC1D_Q_12_inst(.D(MX2_4_Y),.CLK(Q[11]),.CLR(
    ClrAux_7_net),.Q(Q[12]));
DFC1D DFC1D_Q_3_inst(.D(MX2_11_Y),.CLK(Q[2]),.CLR(
    ClrAux_0_net),.Q(Q[3]));
DFC1D DFC1D_Q_4_inst(.D(MX2_5_Y),.CLK(Q[3]),.CLR(
    ClrAux_0_net),.Q(Q[4]));
CM8 CM8_0(.D0(GND),.D1(VCC),.D2(VCC),.D3(GND),.S00(Q[0]),
    .S01(VCC),.S10(Enable),.S11(GND),.Y(CM8_0_Y));
MX2 MX2_11(.A(VCC),.B(GND),.S(Q[3]),.Y(MX2_11_Y));
DFC1B DFC1B_Q_0_inst(.D(CM8_0_Y),.CLK(Clock),.CLR(
    ClrAux_0_net),.Q(Q[0]));
MX2 MX2_6(.A(VCC),.B(GND),.S(Q[2]),.Y(MX2_6_Y));
MX2 MX2_3(.A(VCC),.B(GND),.S(Q[10]),.Y(MX2_3_Y));
DFC1D DFC1D_Q_11_inst(.D(MX2_10_Y),.CLK(Q[10]),.CLR(
    ClrAux_7_net),.Q(Q[11]));
MX2 MX2_10(.A(VCC),.B(GND),.S(Q[11]),.Y(MX2_10_Y));
BUFF BUFF_ClrAux_7_inst(.A(Aclr),.Y(ClrAux_7_net));
MX2 MX2_4(.A(VCC),.B(GND),.S(Q[12]),.Y(MX2_4_Y));
DFC1D DFC1D_Q_5_inst(.D(MX2_9_Y),.CLK(Q[4]),.CLR(
```

```
    ClrAux_0_net), .Q(Q[5]));
DFC1DDFC1D_Q_9_inst(.D(MX2_8_Y), .CLK(Q[8]), .CLR(
    ClrAux_7_net), .Q(Q[9]));
MX2 MX2_5(.A(VCC), .B(GND), .S(Q[4]), .Y(MX2_5_Y));
MX2 MX2_8(.A(VCC), .B(GND), .S(Q[9]), .Y(MX2_8_Y));
DFC1DDFC1D_Q_8_inst(.D(MX2_0_Y), .CLK(Q[7]), .CLR(
    ClrAux_7_net), .Q(Q[8]));
MX2 MX2_2(.A(VCC), .B(GND), .S(Q[6]), .Y(MX2_2_Y));
MX2 MX2_7(.A(VCC), .B(GND), .S(Q[1]), .Y(MX2_7_Y));
MX2 MX2_1(.A(VCC), .B(GND), .S(Q[7]), .Y(MX2_1_Y));
DFC1DDFC1D_Q_6_inst(.D(MX2_2_Y), .CLK(Q[5]), .CLR(
    ClrAux_0_net), .Q(Q[6]));
DFC1DDFC1D_Q_10_inst(.D(MX2_3_Y), .CLK(Q[9]), .CLR(
    ClrAux_7_net), .Q(Q[10]));

endmodule

`timescale 1 ns/100 ps
// Version: 6.2 SP2 6.2.52.7

module decoder_2to4(Data0,Data1,Eq);
input Data0, Data1;
output [3:0] Eq;

    AND2A AND2A_Eq_1_inst(.A(Data1), .B(Data0), .Y(Eq[1]));
    AND2 AND2_Eq_3_inst(.A(Data0), .B(Data1), .Y(Eq[3]));
    AND2A AND2A_Eq_2_inst(.A(Data0), .B(Data1), .Y(Eq[2]));
    AND2B AND2B_Eq_0_inst(.A(Data0), .B(Data1), .Y(Eq[0]));

endmodule

`timescale 1 ns/100 ps
// Version: 6.2 SP2 6.2.52.7

module ram_2048x6(Data,Q,WAddress,RAddress,WE,RE,WClk,RClk);
input [5:0] Data;
output [5:0] Q;
input [10:0] WAddress, RAddress;
input WE, RE, WClk, RClk;

    wire WEP, REP, VCC, GND;

    VCC VCC_1_net(.Y(VCC));
    GND GND_1_net(.Y(GND));
    RAM64K36P ram_2048x6_R0C2(.WCLK(WClk), .RCLK(RClk),
        .DEPTH0(GND), .DEPTH1(GND), .DEPTH2(GND), .DEPTH3(GND),
        .WEN(WEP), .WW0(VCC), .WW1(GND), .WW2(GND), .WRAD0(
        WAddress[0]), .WRAD1(WAddress[1]), .WRAD2(WAddress[2]),
        .WRAD3(WAddress[3]), .WRAD4(WAddress[4]), .WRAD5(
        WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),
        .WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(
        WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),
        .WRAD14(GND), .WRAD15(GND), .WD0(Data[4]), .WD1(Data[5]),
```

.WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),
.WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),
.WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND),
.WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(
GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),
.WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)
, .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(
GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(
RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),
.RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(
RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),
.RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(
RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),
.RDAD14(GND), .RDAD15(GND), .RD0(Q[4]), .RD1(Q[5]), .RD2(
, .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),
.RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),
.RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),
.RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),
.RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),
.RD34(), .RD35());
INVREBUBBLE(.A(RE), .Y(REP));
INVWEBUBBLE(.A(WE), .Y(WEP));
RAM64K36Pram_2048x6_R0C1(.WCLK(WClock), .RCLK(RClock),
.DEPTH0(GND), .DEPTH1(GND), .DEPTH2(GND), .DEPTH3(GND),
.WEN(WEP), .WW0(VCC), .WW1(GND), .WW2(GND), .WRAD0(
WAddress[0]), .WRAD1(WAddress[1]), .WRAD2(WAddress[2]),
.WRAD3(WAddress[3]), .WRAD4(WAddress[4]), .WRAD5(
WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),
.WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(
WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),
.WRAD14(GND), .WRAD15(GND), .WD0(Data[2]), .WD1(Data[3]),
.WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),
.WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),
.WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND)
, .WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(
GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),
.WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)
, .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(
GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(
RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),
.RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(
RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),
.RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(
RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),
.RDAD14(GND), .RDAD15(GND), .RD0(Q[2]), .RD1(Q[3]), .RD2(
, .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),
.RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),
.RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),
.RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),
.RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),
.RD34(), .RD35());
RAM64K36Pram_2048x6_R0C0(.WCLK(WClock), .RCLK(RClock),
.DEPTH0(GND), .DEPTH1(GND), .DEPTH2(GND), .DEPTH3(GND),
.WEN(WEP), .WW0(VCC), .WW1(GND), .WW2(GND), .WRAD0(
WAddress[0]), .WRAD1(WAddress[1]), .WRAD2(WAddress[2]),
.WRAD3(WAddress[3]), .WRAD4(WAddress[4]), .WRAD5(
WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),
.WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(
WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),
.WRAD14(GND), .WRAD15(GND), .WD0(Data[2]), .WD1(Data[3]),
.WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),
.WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),
.WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND)
, .WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(
GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),
.WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)
, .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(
GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(
RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),
.RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(
RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),
.RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(
RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),
.RDAD14(GND), .RDAD15(GND), .RD0(Q[2]), .RD1(Q[3]), .RD2(
, .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),
.RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),
.RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),
.RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),
.RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),
.RD34(), .RD35());

```
WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),  
.WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(  
WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),  
.WRAD14(GND), .WRAD15(GND), .WD0(Data[0]), .WD1(Data[1]),  
.WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),  
.WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),  
.WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND)  
, .WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(  
GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),  
.WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)  
, .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(  
GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(  
RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),  
.RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(  
RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),  
.RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(  
RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),  
.RDAD14(GND), .RDAD15(GND), .RD0(Q[0]), .RD1(Q[1]), .RD2(  
, .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),  
.RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),  
.RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),  
.RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),  
.RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),  
.RD34(), .RD35());
```

endmodule

```
`timescale 1 ns/100ps  
// Version: 6.2 SP2 6.2.52.7
```

```
module mux_6x4(Data0_port,Data1_port,Data2_port,Data3_port,Sel0,  
Sel1,Result);  
input [5:0]Data0_port, Data1_port, Data2_port, Data3_port;  
input Sel0, Sel1;  
output [5:0] Result;
```

```
MX4 MX4_Result_0_inst(.D0(Data0_port[0]), .D1(Data1_port[0]),  
.D2(Data2_port[0]), .D3(Data3_port[0]), .S0(Sel0), .S1(  
Sel1), .Y(Result[0]));  
MX4 MX4_Result_2_inst(.D0(Data0_port[2]), .D1(Data1_port[2]),  
.D2(Data2_port[2]), .D3(Data3_port[2]), .S0(Sel0), .S1(  
Sel1), .Y(Result[2]));  
MX4 MX4_Result_5_inst(.D0(Data0_port[5]), .D1(Data1_port[5]),  
.D2(Data2_port[5]), .D3(Data3_port[5]), .S0(Sel0), .S1(  
Sel1), .Y(Result[5]));  
MX4 MX4_Result_1_inst(.D0(Data0_port[1]), .D1(Data1_port[1]),  
.D2(Data2_port[1]), .D3(Data3_port[1]), .S0(Sel0), .S1(  
Sel1), .Y(Result[1]));  
MX4 MX4_Result_4_inst(.D0(Data0_port[4]), .D1(Data1_port[4]),  
.D2(Data2_port[4]), .D3(Data3_port[4]), .S0(Sel0), .S1(  
Sel1), .Y(Result[4]));  
MX4 MX4_Result_3_inst(.D0(Data0_port[3]), .D1(Data1_port[3]),  
.D2(Data2_port[3]), .D3(Data3_port[3]), .S0(Sel0), .S1(  
Sel1), .Y(Result[3]));
```

endmodule



Microsemi Headquarters
One Enterprise, Aliso Viejo,
CA 92656 USA
Within the USA: +1 (800) 713-4113
Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 380-6136
Fax: +1 (949) 215-4996
Email: AVO-sales.support@microchip.com
www.microsemi.com

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